

# LP503x 36/30 通道 12 位 PWM 超低静态电流 I<sup>2</sup>C RGB LED 驱动器

## 1 特性

- 工作电压范围：
  - V<sub>CC</sub> 范围：2.7V 至 5.5V
  - 与 1.8V、3.3V 和 5V 电源轨兼容的 EN、SDA 和 SCL 引脚
  - 最大输出电压：6V
- 36 路高精度恒定电流阱
  - 在整个 V<sub>CC</sub> 范围内，每个通道的最大电流为 25.5mA
  - 当 V<sub>CC</sub> ≥ 3.3V 时，每个通道的最大电流为 35mA
  - 器件间的误差为 ±5%；通道间的误差为 ±5%
- 超低静态电流：
  - 关断模式：1μA（最大值），EN 处于低电平
  - 省电模式：12μA（最大值），EN 处于高电平，所有 LED 关断时间大于 30ms
- 每个通道具有一个集成式 12 位 29kHz PWM 发生器：
  - 每个通道具有一个独立的色彩混合寄存器
  - 每个 RGB LED 模块具有一个独立的亮度控制寄存器
  - 可选的对数或线性标度亮度控制
  - 集成式三相相移 PWM 方案
- 3 个可编程组（R、G、B），可轻松对每种颜色进行软件控制
- 2 个外部硬件地址引脚允许连接多达 4 个器件
- 广播从地址允许同时配置多个器件
- 自动递增允许在一次传输期间写入或读取多个连续的寄存器
- 高达 400kHz 的快速模式 I<sup>2</sup>C 速度

## 2 应用

用于以下设备的 LED 照明、指示灯和闪烁光：

- 智能扬声器
- 智能家用电器
- 可视门铃
- 电子智能锁
- 烟雾探测器
- 机顶盒
- 智能路由器
- 手持设备

## 3 说明

高效、高性能的 LED 响应效果，如闪烁，呼吸和追逐，对于改善许多人机界面 (HMI) 应用中的最终用户体验 至关重要。

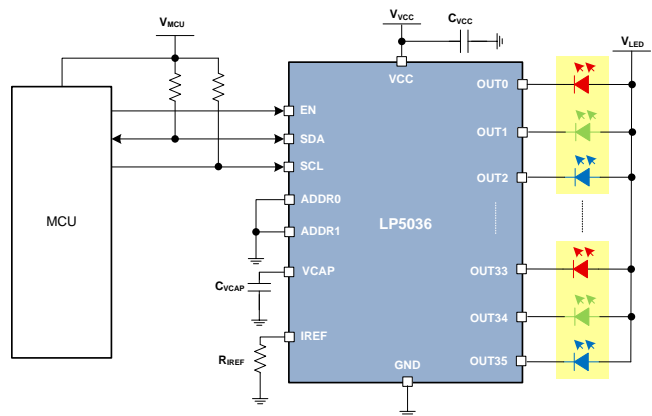
LP503x 器件是一款 30 或 36 通道恒定电流阱 LED 驱动器。LP503x 具有适用于每个通道的 29kHz、12 位 PWM 发生器以及通道/模块独立的色彩混合和强度控制（之前被称为亮度控制寄存器），能够达到可闻噪声为零的生动 LED 效果。用户可以受益于器件的超低关断 I<sub>q</sub> 省电模式，而设计人员可以借助 LP503x 的三个可编程组（R G B）非常轻松地地为软件编码。

器件信息<sup>(1)</sup>

器件型号	封装	封装尺寸（标称值）
LP5030	VQFN (46)	6.00mm × 5.00mm
LP5036		

(1) 如需了解所有可用封装，请参阅数据表末尾的可订购产品附录。

简化原理图



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## 4 修订历史记录

注：之前版本的页码可能与当前版本有所不同。

<b>Changes from Revision A (December 2018) to Revision B</b>	<b>Page</b>
• Changed max standby current from 10uA to 12uA .....	<b>8</b>
• Changed power-save mode current from 10uA to 12uA .....	<b>8</b>
• 已更改 from LED3 to LED11 .....	<b>28</b>

<b>Changes from Original (September 2018) to Revision A</b>	<b>Page</b>
• 首次发布生产数据数据表 .....	<b>1</b>

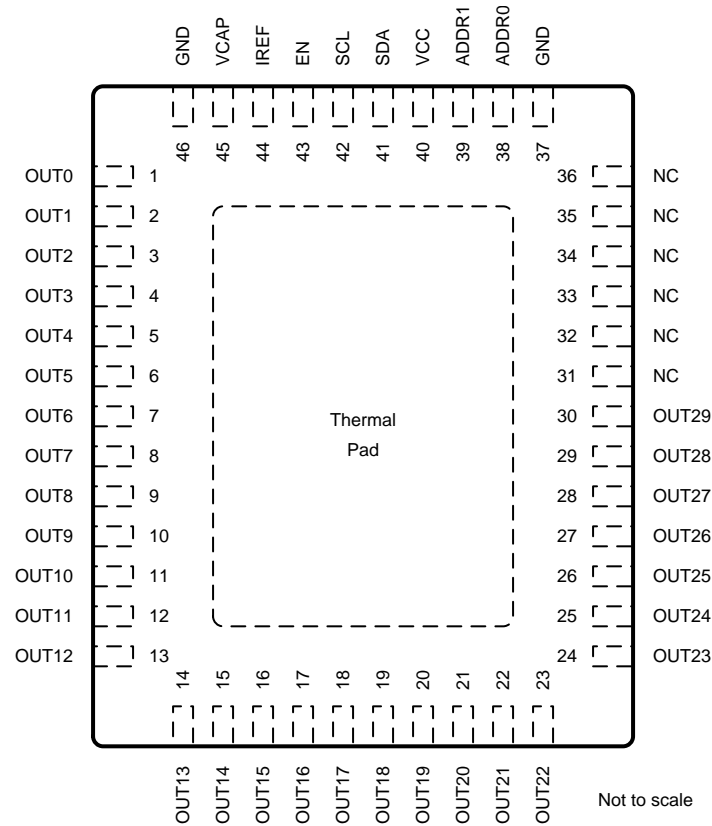
## 5 说明（续）

LP503x 器件以 12 位 PWM 分辨率和 29kHz 开关频率控制每个 LED 输出。这种控制有助于获得可平缓降低的强度并消除可闻噪声。该器件具有不同的色彩混合和强度控制寄存器，使得编写软件代码变得非常简单。在以淡入淡出类型的呼吸效果为目标时，全局 R、G、B 组控制可显著减轻微控制器负载。LP503x 器件还可以实现 PWM 相移功能，以帮助在多个 LED 同时打开时降低输入功率预算。

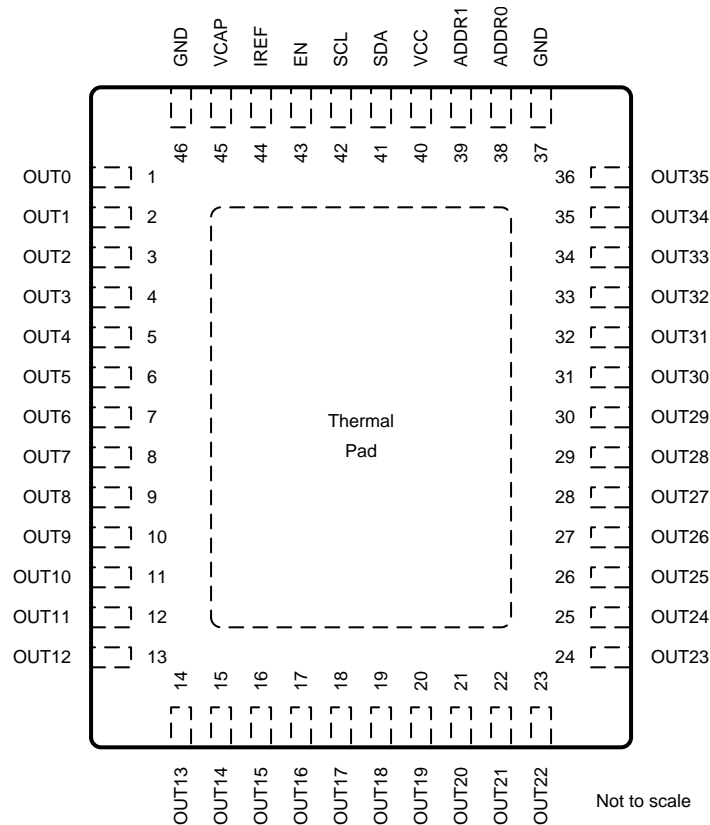
LP503x 器件具有自动省电模式，可实现超低静态电流。当所有通道都关断 30ms 时，该器件的总功耗会降至 10 $\mu$ A，这使得 LP503x 器件成为电池供电终端设备的可能替代产品。

## 6 Pin Configuration and Functions

**LP5030 RJV Package  
46-Pin VQFN With Exposed Thermal Pad  
Top View**



**LP5036 RJV Package  
46-Pin VQFN With Exposed Thermal Pad  
Top View**



**Pin Functions**

PIN			I/O	DESCRIPTION
NAME	NO.			
	LP5030	LP5036		
ADDR0	38	38	—	I <sup>2</sup> C slave-address selection pin. This pin must not be left floating.
ADDR1	39	39	—	I <sup>2</sup> C slave-address selection pin. This pin must not be left floating.
EN	43	43	I	Chip enable input pin
IREF	44	44	—	Output current-reference global-setting pin
NC	31	—	—	No internal connection
NC	32	—	—	No internal connection
NC	33	—	—	No internal connection
NC	34	—	—	No internal connection
NC	35	—	—	No internal connection
NC	36	—	—	No internal connection
OUT0	1	1	O	Current sink output 0. If not used, this pin can be left floating.
OUT1	2	2	O	Current sink output 1. If not used, this pin can be left floating.
OUT2	3	3	O	Current sink output 2. If not used, this pin can be left floating.
OUT3	4	4	O	Current sink output 3. If not used, this pin can be left floating.
OUT4	5	5	O	Current sink output 4. If not used, this pin can be left floating.
OUT5	6	6	O	Current sink output 5. If not used, this pin can be left floating.
OUT6	7	7	O	Current sink output 6. If not used, this pin can be left floating.

**Pin Functions (continued)**

NAME	PIN NO.		I/O	DESCRIPTION
	LP5030	LP5036		
OUT7	8	8	O	Current sink output 7. If not used, this pin can be left floating.
OUT8	9	9	O	Current sink output 8. If not used, this pin can be left floating.
OUT9	10	10	O	Current sink output 9. If not used, this pin can be left floating.
OUT10	11	11	O	Current sink output 10. If not used, this pin can be left floating.
OUT11	12	12	O	Current sink output 11. If not used, this pin can be left floating.
OUT12	13	13	O	Current sink output 12. If not used, this pin can be left floating.
OUT13	14	14	O	Current sink output 13. If not used, this pin can be left floating.
OUT14	15	15	O	Current sink output 14. If not used, this pin can be left floating.
OUT15	16	16	O	Current sink output 15. If not used, this pin can be left floating.
OUT16	17	17	O	Current sink output 16. If not used, this pin can be left floating.
OUT17	18	18	O	Current sink output 17. If not used, this pin can be left floating.
OUT18	19	19	O	Current sink output 18. If not used, this pin can be left floating.
OUT19	20	20	O	Current sink output 19. If not used, this pin can be left floating.
OUT20	21	21	O	Current sink output 20. If not used, this pin can be left floating.
OUT21	22	22	O	Current sink output 21. If not used, this pin can be left floating.
OUT22	23	23	O	Current sink output 22. If not used, this pin can be left floating.
OUT23	24	24	O	Current sink output 23. If not used, this pin can be left floating.
OUT24	25	25	O	Current sink output 24. If not used, this pin can be left floating.
OUT25	26	26	O	Current sink output 25. If not used, this pin can be left floating.
OUT26	27	27	O	Current sink output 26. If not used, this pin can be left floating.
OUT27	28	28	O	Current sink output 27. If not used, this pin can be left floating.
OUT28	29	29	O	Current sink output 28. If not used, this pin can be left floating.
OUT29	30	30	O	Current sink output 29. If not used, this pin can be left floating.
OUT30	—	31	O	Current sink output 30. If not used, this pin can be left floating.
OUT31	—	32	O	Current sink output 31. If not used, this pin can be left floating.
OUT32	—	33	O	Current sink output 32. If not used, this pin can be left floating.
OUT33	—	34	O	Current sink output 33. If not used, this pin can be left floating.
OUT34	—	35	O	Current sink output 34. If not used, this pin can be left floating.
OUT35	—	36	O	Current sink output 35. If not used, this pin can be left floating.
SCL	42	42	I	I <sup>2</sup> C bus clock line. If not used, this pin must be connected to GND or VCC.
SDA	41	41	I/O	I <sup>2</sup> C bus data line. If not used, this pin must be connected to GND or VCC.
VCAP	45	45	—	Internal LDO output pin, this pin must be connected to a 1-μF capacitor to GND.
VCC	40	40	I	Input power.
GND	37	37	—	The ground pin for the device.
GND	46	46	—	The ground pin for the device.
Thermal pad	GND	GND	—	Exposed thermal pad also serves as a ground for the device.

## 7 Specifications

### 7.1 Absolute Maximum Ratings

over operating ambient temperature range (unless otherwise noted)<sup>(1)</sup>

	MIN	MAX	UNIT
Voltage on EN, IREF, OUTx, SCL, SDA, VCC	−0.3	6	V
Voltage on ADDR <sub>x</sub>	−0.3	VCC+0.3	V
Voltage on VCAP	−0.3	2	V
Continuous power dissipation	Internally limited		
Junction temperature, T <sub>J-MAX</sub>	−40	125	°C
Storage temperature, T <sub>stg</sub>	−65	150	°C

- (1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions*. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

### 7.2 ESD Ratings

		VALUE	UNIT
V <sub>(ESD)</sub>	Electrostatic discharge	Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001 <sup>(1)</sup>	±4000
		Charged-device model (CDM), per JEDEC specification JESD22-C101 <sup>(2)</sup>	±1500

- (1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process. Pins listed as ±1500 V may actually have higher performance.
- (2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process. Pins listed as ±500 V may actually have higher performance.

### 7.3 Recommended Operating Conditions

over operating ambient temperature range (unless otherwise noted)

	MIN	MAX	UNIT
Input voltage on VCC	2.7	5.5	V
Voltage on OUT <sub>x</sub>	0	5.5	V
Voltage on ADDR <sub>x</sub> , EN, SDA, SCL	0	5.5	V
Operating ambient temperature, T <sub>A</sub>	−40	85	°C

### 7.4 Thermal Information

THERMAL METRIC <sup>(1)</sup>		LP5030 or LP5036	UNIT
		RJV (QFN)	
		46 PINS	
R <sub>θJA</sub>	Junction-to-ambient thermal resistance	35.7	°C/W
R <sub>θJC(top)</sub>	Junction-to-case (top) thermal resistance	29.1	°C/W
R <sub>θJB</sub>	Junction-to-board thermal resistance	16.2	°C/W
ψ <sub>JT</sub>	Junction-to-top characterization parameter	0.9	°C/W
ψ <sub>JB</sub>	Junction-to-board characterization parameter	16.2	°C/W
R <sub>θJC(bot)</sub>	Junction-to-case (bottom) thermal resistance	6.3	°C/W

- (1) For more information about traditional and new thermal metrics, see [Semiconductor and ICPackage Thermal Metrics](#).

## 7.5 Electrical Characteristics

 over operating ambient temperature range ( $-40^{\circ}\text{C} < T_A < 85^{\circ}\text{C}$ ) (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
POWER SUPPLIES (VCC)						
V <sub>VCC</sub>	Supply voltage <sup>(1)</sup>		2.7		5.5	V
I <sub>VCC</sub>	Shutdown supply current	V <sub>EN</sub> = 0 V		0.2	1	μA
	Standby supply current	V <sub>EN</sub> = 3.3 V, Chip_EN = 0 (bit)		6	12	
	Normal-mode supply current	With 10-mA LED current per OUTx		6.5	10	mA
	Power-save mode supply current	V <sub>EN</sub> = 3.3 V, Chip_EN = 1 (bit), Power_Save_EN = 1 (bit), all the LEDs off duration > t <sub>PSM</sub>		6	12	μA
V <sub>UVR</sub>	Undervoltage restart	V <sub>VCC</sub> rising			2.5	V
V <sub>UVF</sub>	Undervoltage shutdown	V <sub>VCC</sub> falling	2			V
V <sub>UV_HYS</sub>	Undervoltage shutdown hysteresis			0.2		V
OUTPUT STAGE (OUTx)						
I <sub>MAX</sub>	Maximum sink current (OUT0 – OUT35)	V <sub>VCC</sub> in full range, Max_Current_Option = 0 (bit), PWM = 100%			25.5	mA
	Maximum sink current (OUT0 – OUT35)	V <sub>VCC</sub> ≥ 3.3 V, Max_Current_Option = 1 (bit), PWM = 100%			35	
I <sub>LIM</sub>	Internal sink current limit (OUT0 – OUT35)	V <sub>VCC</sub> in full range, Max_Current_Option = 0 (bit), V <sub>IREF</sub> = 0 V	35	55	80	mA
	Internal sink current limit (OUT0 – OUT35)	V <sub>VCC</sub> ≥ 3.3V, Max_Current_Option=1 (bit), V <sub>IREF</sub> = 0 V	40	75	120	
I <sub>LKG</sub>	Leakage current (OUT0 – OUT35)	PWM = 0%		0.1	1	μA
I <sub>ERR_DD</sub>	Device to device current error, I <sub>ERR_DD</sub> =(I <sub>AVE</sub> -I <sub>SET</sub> )/I <sub>SET</sub> ×100%	V <sub>VCC</sub> = 3.3V. All channels' current set to 10 mA. PWM = 100%. Already includes the V <sub>IREF</sub> and K <sub>IREF</sub> tolerance	–5%		5%	
I <sub>ERR_CC</sub>	Channel to channel current error, I <sub>ERR_CC</sub> =(I <sub>OUTX</sub> -I <sub>AVE</sub> )/I <sub>AVE</sub> ×100%	V <sub>VCC</sub> = 3.3V. All channels' current set to 10 mA. PWM = 100%. Already includes the V <sub>IREF</sub> and K <sub>IREF</sub> tolerance	–5%		5%	
V <sub>IREF</sub>	IREF voltage <sup>(1)</sup>			0.7		V
K <sub>IREF</sub>	IREF ratio <sup>(1)</sup>			105		
f <sub>PWM</sub>	PWM switching frequency <sup>(1)</sup>		21	29		kHz
V <sub>SAT</sub>	Output saturation voltage	V <sub>VCC</sub> in full range, Max_Current_Option = 0 (bit), output current set to 20 mA, the voltage when the LED current has dropped 5%		0.25	0.35	V
		V <sub>VCC</sub> ≥ 3.3 V, Max_Current_Option = 1 (bit), output current set to 20 mA, the voltage when the LED current has dropped 5%		0.3	0.4	
LOGIC INPUTS (EN, SCL, SDA, ADDR <sub>x</sub> )						
V <sub>IL</sub>	Low level input voltage				0.4	V
V <sub>IH</sub>	High level input voltage		1.4			V
I <sub>LOGIC</sub>	Input current		–1		1	μA
V <sub>SDA</sub>	SDA output low level	I <sub>PULLUP</sub> = 5 mA			0.4	V

(1) Specified by design

## Electrical Characteristics (continued)

over operating ambient temperature range ( $-40^{\circ}\text{C} < T_A < 85^{\circ}\text{C}$ ) (unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
<b>PROTECTION CIRCUITS</b>					
$T_{(TSD)}$	Thermal-shutdown junction temperature <sup>(1)</sup>		160		$^{\circ}\text{C}$
$T_{(HYS)}$	Thermal shutdown temperature hysteresis <sup>(1)</sup>		15		$^{\circ}\text{C}$

## 7.6 Timing Requirements

over operating ambient temperature range ( $-40^{\circ}\text{C} < T_A < 85^{\circ}\text{C}$ ) (unless otherwise noted)

		MIN	TYP	MAX	UNIT
$f_{\text{OSC}}$	Internal oscillator frequency <sup>(1)</sup>		15		MHz
$t_{\text{PSM}}$	Power save mode deglitch time <sup>(1)</sup>	20	30	40	ms
$t_{\text{EN\_H}}$	EN first rising edge until first I <sup>2</sup> C access <sup>(1)</sup>			500	$\mu\text{s}$
$t_{\text{EN\_L}}$	EN first falling edge until first I <sup>2</sup> C reset <sup>(1)</sup>			3	$\mu\text{s}$
$f_{\text{SCL}}$	I <sup>2</sup> C clock frequency <sup>(1)</sup>			400	kHz
1	Hold time (repeated) START condition <sup>(1)</sup>	0.6			$\mu\text{s}$
2	Clock low time <sup>(1)</sup>	1.3			$\mu\text{s}$
3	Clock high time <sup>(1)</sup>	600			ns
4	Setup time for a repeated START condition <sup>(1)</sup>	600			ns
5	Data hold time <sup>(1)</sup>	0			ns
6	Data setup time <sup>(1)</sup>	100			ns
7	Rise time of SDA and SCL <sup>(1)</sup>	$20 + 0.1 C_b$			ns
8	Fall time of SDA and SCL <sup>(1)</sup>	$15 + 0.1 C_b$			ns
9	Setup time for STOP condition <sup>(1)</sup>	600			ns
10	Bus free time between a STOP and a START condition <sup>(1)</sup>	1.3			$\mu\text{s}$
$C_b$	Capacitive load parameter for each bus line Load of 1 pF corresponds to one nanosecond <sup>(1)</sup> .	10		200	pF

(1) Specified by design

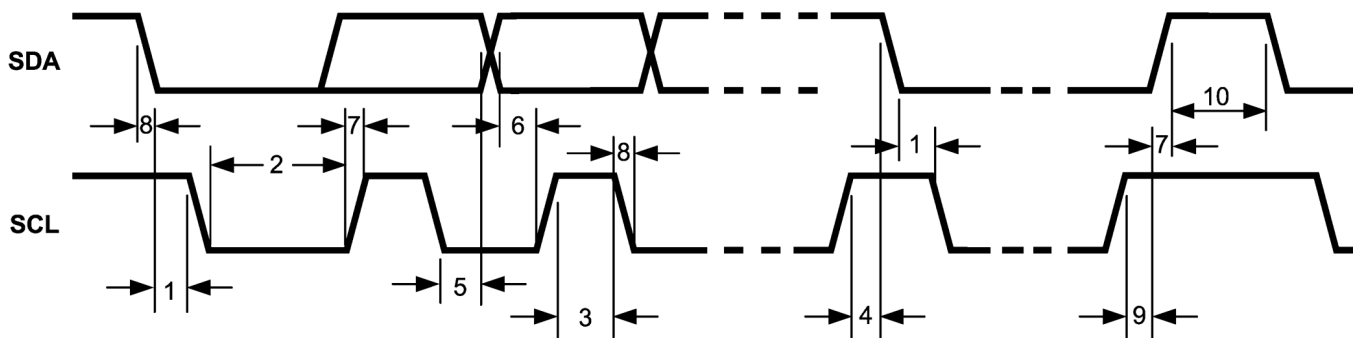


图 1. I<sup>2</sup>C Timing Parameters

## 7.7 Typical Characteristics

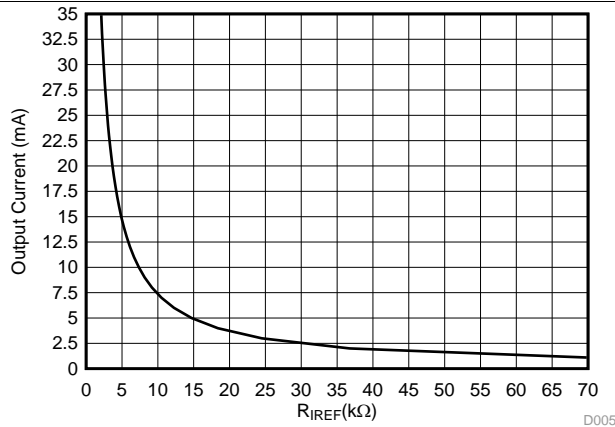


图 2. Output Current Target vs  $R_{IREF}$

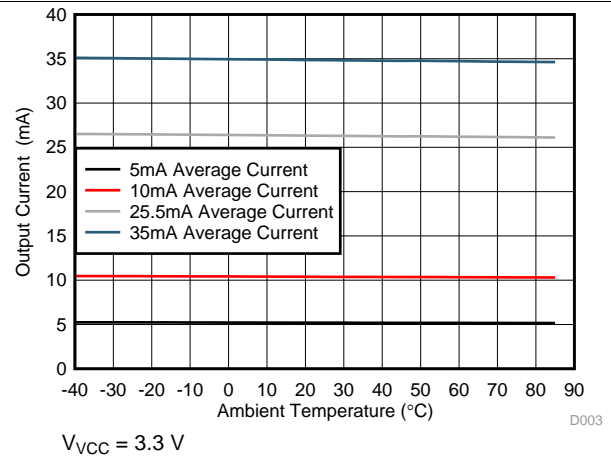


图 3. Output Current vs Ambient Temperature

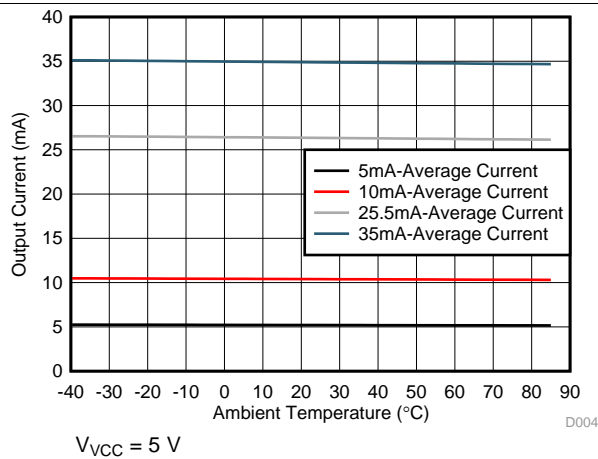


图 4. Output Current vs Ambient Temperature

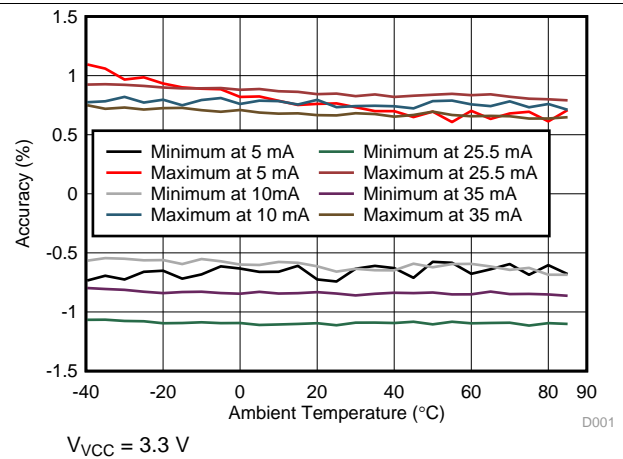


图 5. Channel-to-Channel Accuracy

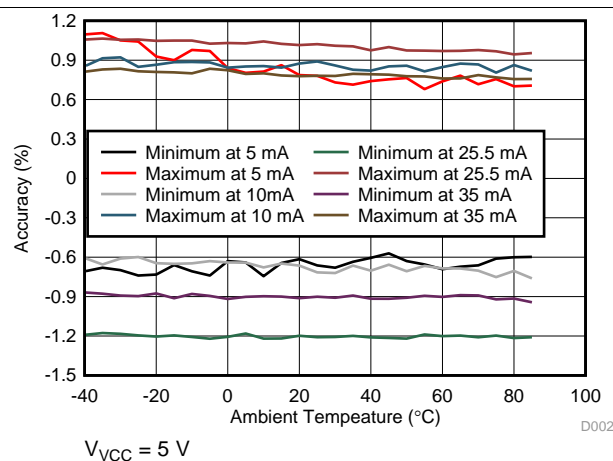


图 6. Channel-to-Channel Accuracy

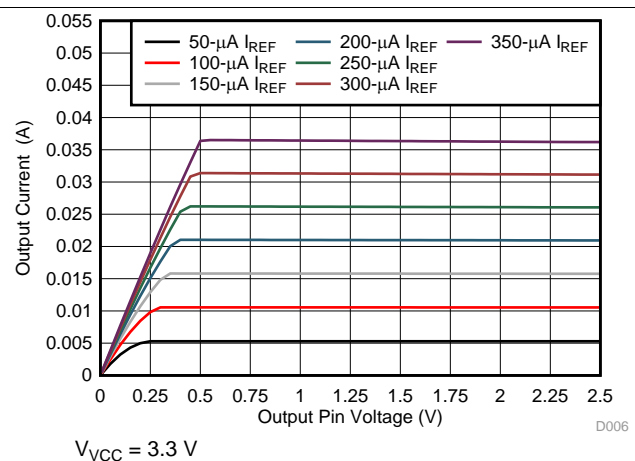


图 7. OUT Pin Voltage vs Current

## Typical Characteristics (接下页)

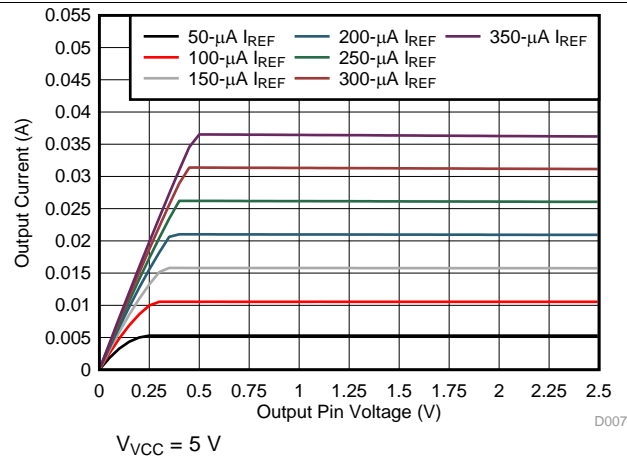


图 8. OUT Pin Voltage vs Current

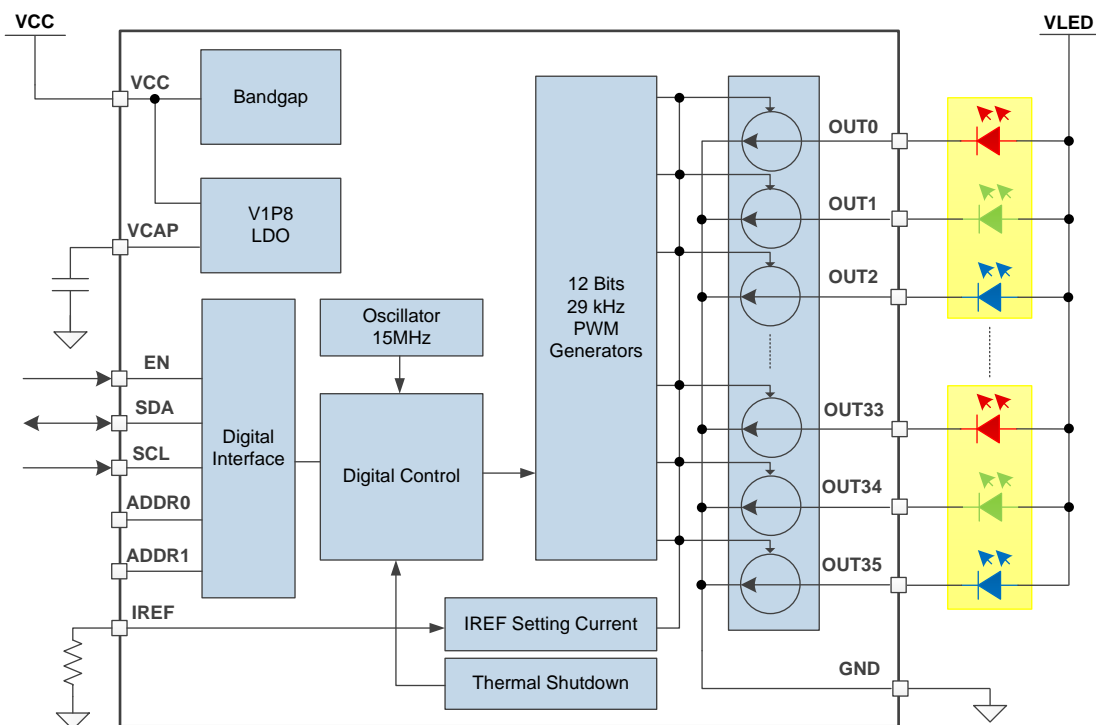
## 8 Detailed Description

### 8.1 Overview

The LP503x device is a 30- or 36-channel constant-current-sink LED driver. The LP503x device includes all necessary power rails, an on-chip oscillator, and a two-wire serial I<sup>2</sup>C interface. The maximum constant-current value of all channels is set by a single external resistor. Two hardware address pins allow up to four devices on the same bus. An automatic power-saving mode is implemented to keep the total current consumption under 10  $\mu$ A, which makes the LP503x device a potential choice for battery-powered end-equipment.

The LP503x device is optimized for RGB LEDs regarding both live effects and software efforts. The LP503x device controls each LED output with 12-bit PWM resolution at 29-kHz switching frequency, which helps achieve a smooth dimming effect and eliminates audible noise. The independent color-mixing and intensity-control registers make the software coding straightforward. When targeting a fade-in, fade-out type breathing effect, the global RGB bank control reduces the microcontroller loading significantly. The LP503x device also implements a PWM phase-shifting function to help reduce the input power budget when LEDs turn on simultaneously.

### 8.2 Functional Block Diagram



### 8.3 Feature Description

#### 8.3.1 Each Channel PWM Control

Most traditional LED drivers are designed for the single-color LEDs, in which the high resolution PWM generator is used for intensity control only. However, for RGB LEDs, both the color mixing and intensity control should be addressed to achieve the target effect. With the traditional solution, the users must handle the color mixing and intensity control simultaneously with a single PWM register. Several undesired effects occur: the limited dimming steps, the complex software design, and the color distortion when using a logarithmic scale control.

The LP503x device is designed with independent color mixing and intensity control, which makes the RGB LED effects fancy and the control experience straightforward. With the inputs of the color-mixing register and the intensity-control register, the final PWM generator output for each channel is 12-bit resolution and 29-kHz dimming frequency, which helps achieve a smooth dimming effect and eliminates audible noise. See [Figure 9](#).

## Feature Description (接下页)

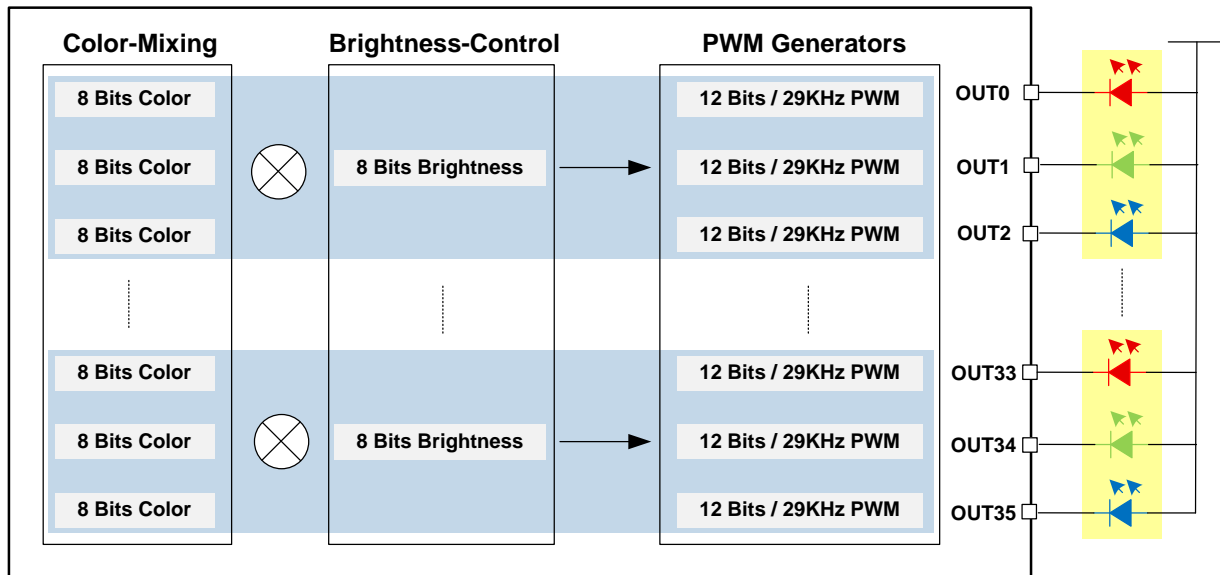


图 9. PWM Control Scheme for Each Channel

### 8.3.1.1 Independent Color Mixing Per RGB LED Module

Each output channel has its own individual 8-bit color-setting register (OUTx\_COLOR). The device allows every RGB LED module to achieve >16 million ( $256 \times 256 \times 256$ ) color-mixing.

### 8.3.1.2 Independent Intensity Control Per RGB LED Module

When color is fixed, the independent intensity-control is used to achieve accurate and flexible dimming control for every RGB LED module.

#### 8.3.1.2.1 Intensity-Control Register Configuration

Every three consecutive output channels are assigned to their respective intensity-control register (LEDx\_BRIGHTNESS). For example, OUT0, OUT1, and OUT2 are assigned to LED0\_BRIGHTNESS, so it is recommended to connect the RGB LEDs in the sequence as shown in 表 1. The LP503x device allows 256-step intensity control for each RGB LED module, which helps achieve a smooth dimming effect.

Keeping FFh (default value) in the LED0\_BRIGHTNESS register results in 100% dimming duty cycle. With this setting, the users can just configure the color mixing register by channel to achieve the target dimming effect in a single-color LED application.

#### 8.3.1.2.2 Logarithmic- or Linear-Scale Intensity Control

For human-eye-friendly visual performance, a logarithmic-scale dimming curve is usually implemented in LED drivers. However, for RGB LEDs, if using a single register to achieve both color mixing and intensity control, color distortion can be observed easily when using a logarithmic scale. The LP503x device, with independent color-mixing and intensity-control registers, implements the logarithmic scale dimming control inside the intensity control function, which solves the color distortion issue effectively. See 图 10. Also, the LP503x device allows users to configure the dimming scale either logarithmically or linearly through the global Log\_Scale\_EN register bit. If a special dimming curve is desired, using the linear scale with software correction is the most flexible approach. See 图 11.

## Feature Description (接下页)

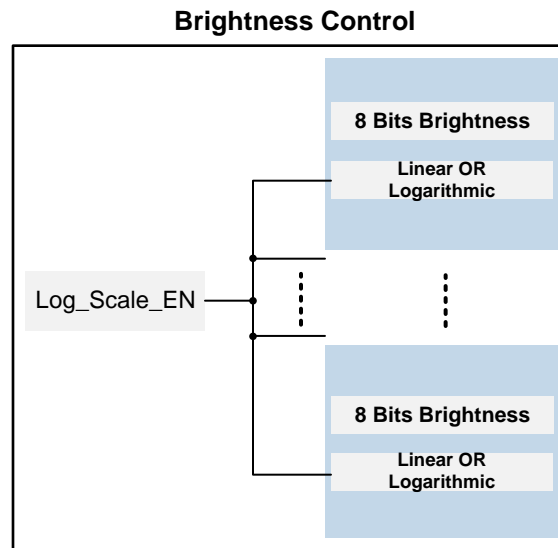


图 10. Logarithmic or Linear Scale Intensity Control

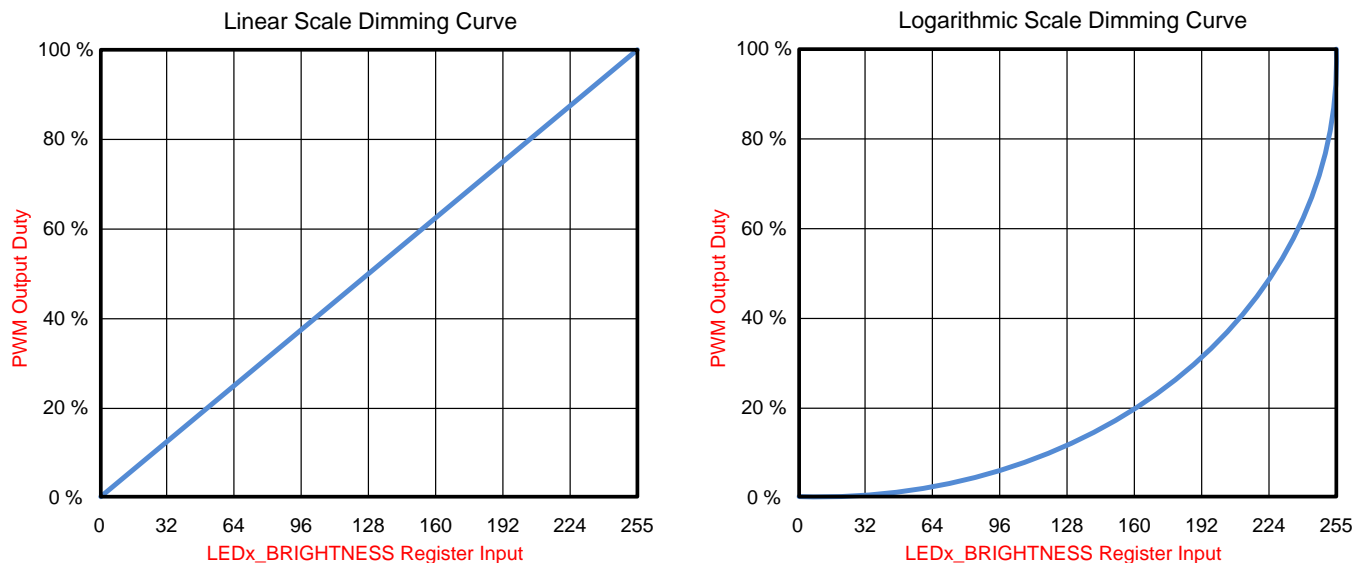


图 11. Logarithmic vs Linear Dimming Curve

### 8.3.1.3 12-Bit, 29-kHz PWM Generator Per Channel

#### 8.3.1.3.1 PWM Generator

With the inputs of the color mixing and the intensity control, the final output PWM duty cycle is defined as the product obtained by multiplying the color-mixing register value by the related intensity-control register value. The final output PWM duty cycle has 12 bits of control accuracy, which is achieved by a 9 bits of pure PWM resolution and 3 bits of dithering digital control. For 3-bit dithering, every eighth pulse is made 1 LSB longer to increase the average value by 1 / 8th. The LP503x device allows the users to enable or disable the dithering function through the PWM\_Dithering\_EN register. When enabled (default), the output PWM duty-cycle accuracy is 12 bits. When disabled, the output PWM duty-cycle accuracy is 9 bits.

To eliminate the audible noise due to the PWM switching, the LP503x device sets the PWM switching frequency at 29-kHz, above the 20-kHz human hearing range.

## Feature Description (接下页)

### 8.3.1.4 PWM Phase-Shifting

A PWM phase-shifting scheme allows delaying the time when each LED driver is active. When the LED drivers are not activated simultaneously, the peak load current from the pre-stage power supply is significantly decreased. The scheme also reduces input-current ripple and ceramic-capacitor audible ringing. LED drivers are grouped into three different phases.

- Phase 1—the rising edge of the PWM pulse is fixed. The falling edge of the pulse is changed when the duty cycle changes. Phase 1 is applied to LED0, LED3, ..., LED[3 × (n – 1)].
- Phase 2—the middle point of the PWM pulse is fixed. The pulse spreads in both directions when the PWM duty cycle is increased. Phase 2 is applied to LED1, LED4, ..., LED[3 × (n – 1) + 1].
- Phase 3—the falling edge of the PWM pulse is fixed. The rising edge of the pulse is changed when the duty cycle changes. Phase 3 is applied to LED2, LED5, ..., LED[3 × (n – 1) + 2].
- For LP5030, n = 10. For LP5036, n = 12.

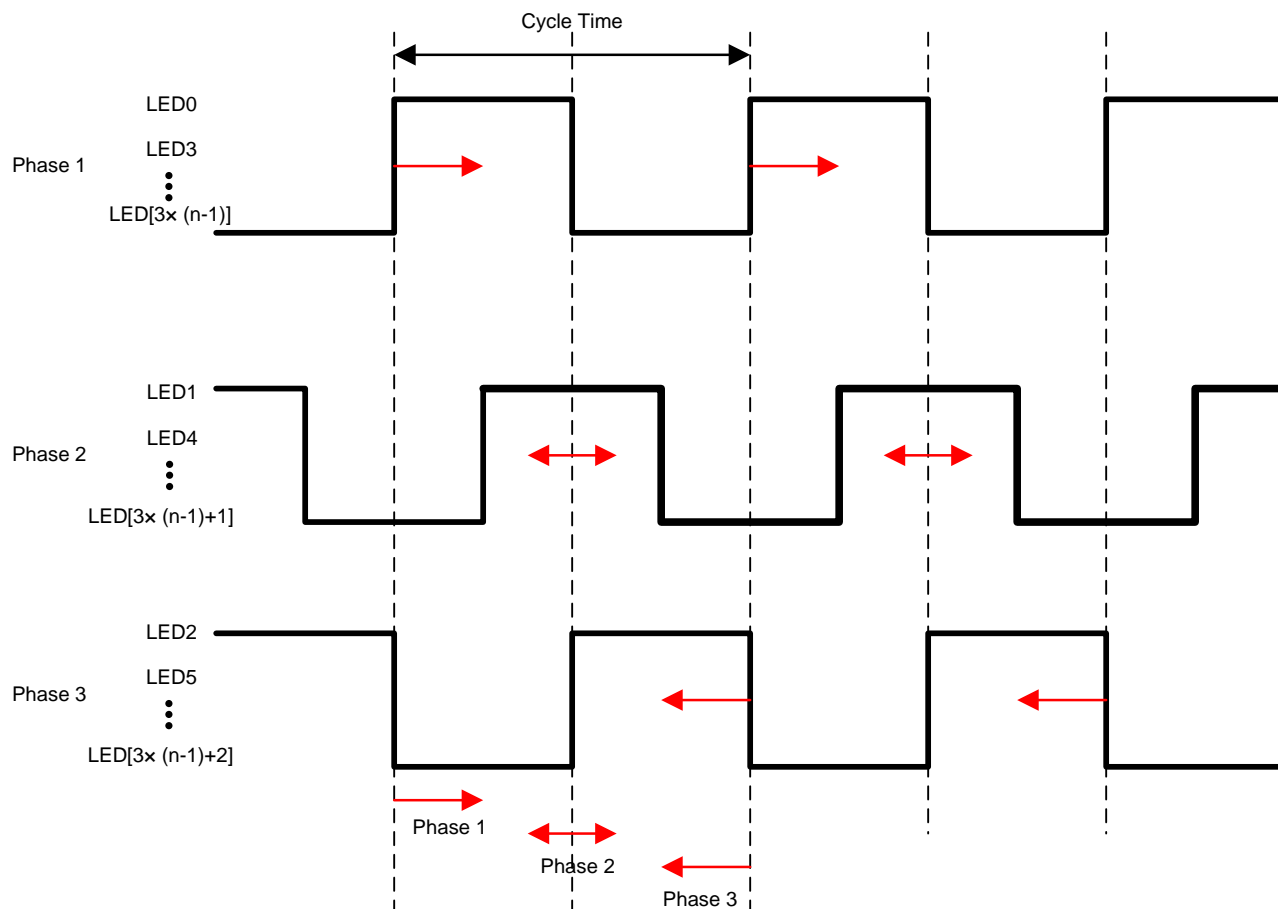


图 12. PWM Phase-Shifting

### 8.3.2 LED Bank Control

For most LED-animation effects, like blinking and breathing, all the RGB LEDs have the same lighting pattern. Instead of controlling the individual LED separately, which occupies the microcontroller resources heavily, the LP503x device provides an easy coding approach, the LED bank control.

## Feature Description (接下页)

Each channel can be configured as either independent control or bank control through the LEDx\_Bank\_EN register. When LEDx\_Bank\_EN = 0 (default), the LED is controlled independently by the related color-mixing and intensity-control registers. When LEDx\_Bank\_EN = 1, the LP503x device drives the LED in LED bank-control mode. The LED bank has its own independent PWM control scheme, which is the same structure as the PWM scheme of each channel. See [Each Channel PWM Control](#) for more details. When a channel configured as LED bank-control mode, the related color mixing and intensity control is governed by the bank control registers (BANK\_A\_COLOR, BANK\_B\_COLOR, BANK\_C\_COLOR, and BANK\_BRIGHTNESS) regardless of the inputs on its own color-mixing and intensity-control registers.

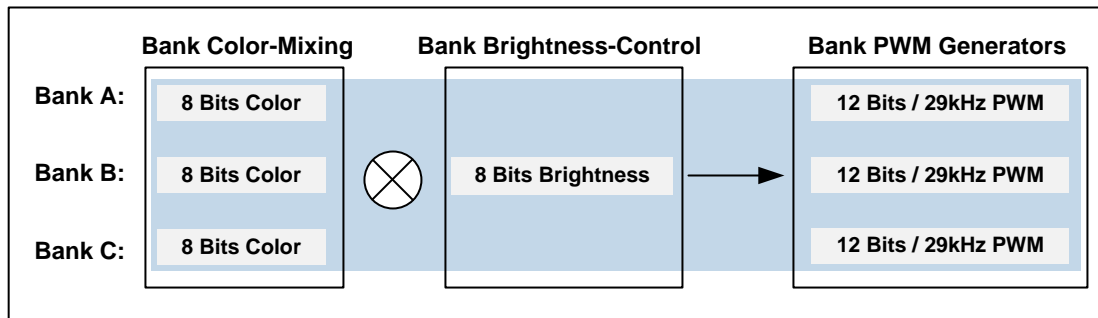


图 13. Bank PWM Control Scheme

表 1. Bank Number and LED Number Assignment

OUT NUMBER	BANK NUMBER	RGB LED MODULE NUMBER
OUT0	Bank A	LED0
OUT1	Bank B	
OUT2	Bank C	
OUT3	Bank A	LED1
OUT4	Bank B	
OUT5	Bank C	
OUT6	Bank A	LED2
OUT7	Bank B	
OUT8	Bank C	
OUT9	Bank A	LED3
OUT10	Bank B	
OUT11	Bank C	
OUT12	Bank A	LED4
OUT13	Bank B	
OUT14	Bank C	
OUT15	Bank A	LED5
OUT16	Bank B	
OUT17	Bank C	
OUT18	Bank A	LED6
OUT19	Bank B	
OUT20	Bank C	
OUT21	Bank A	LED7
OUT22	Bank B	
OUT23	Bank C	
OUT24	Bank A	LED8
OUT25	Bank B	
OUT26	Bank C	

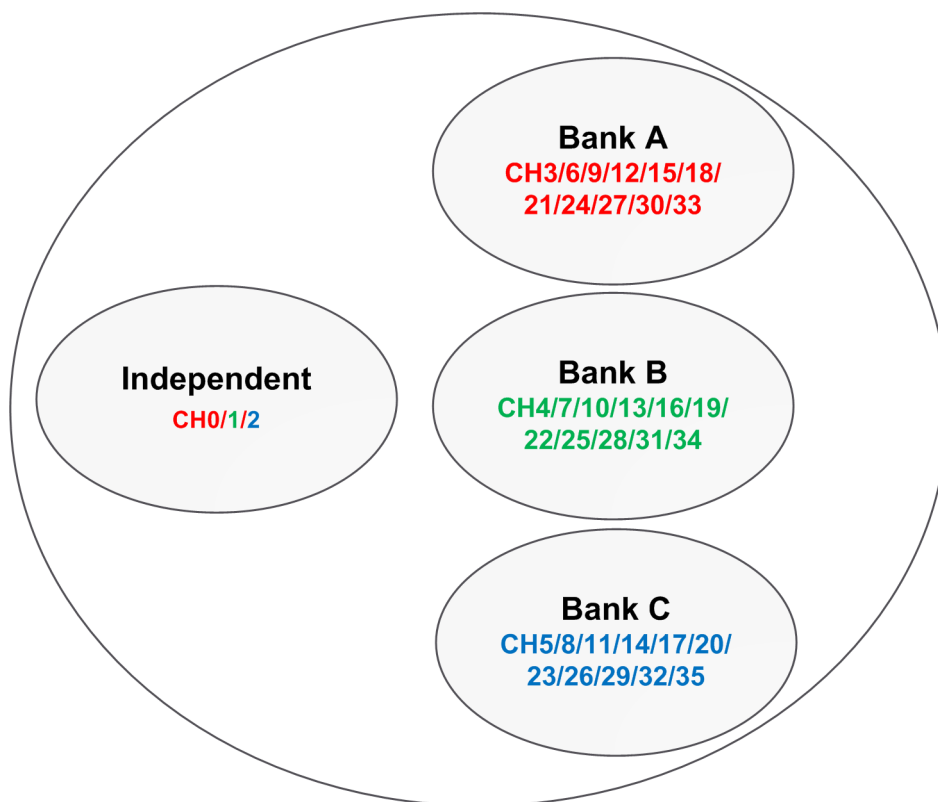
## Feature Description (接下页)

**表 1. Bank Number and LED Number Assignment (接下页)**

OUT NUMBER	BANK NUMBER	RGB LED MODULE NUMBER
OUT27	Bank A	LED9
OUT28	Bank B	
OUT29	Bank C	
OUT30	Bank A	LED10 <sup>(1)</sup>
OUT31	Bank B	
OUT32	Bank C	
OUT33	Bank A	LED11 <sup>(1)</sup>
OUT34	Bank B	
OUT35	Bank C	

(1) For LP5036 only.

With the bank control configuration, the LP503x device enables users to achieve smooth and live LED effects globally with an ultra-simple software effort. 图 14 shows an example using LED0 as an independent RGB indicator and others with group breathing effect.



**图 14. Bank PWM Control Example**

### 8.3.3 Current Range Setting

The maximum constant-current value of all 30 or 36 channels is set by a single external resistor,  $R_{IREF}$ . The value of  $R_{IREF}$  can be calculated by 公式 1.

$$R_{IREF} = K_{IREF} \times \frac{V_{IREF}}{I_{SET}}$$

where:

- $K_{IREF} = 105$
  - $V_{IREF} = 0.7 \text{ V}$
- (1)

With the IREF pin floating, the output current is close to zero. With the IREF pin shorted to GND, the LP503x device provides internal current-limit protection, and the output-channel maximum current is limited to  $I_{LIM}$ .

The LP503x device supports two levels of maximum output current,  $I_{MAX}$ .

- When  $V_{CC}$  is in the range from 2.7 V to 5.5 V, and the Max\_Current\_Option (bit) = 0,  $I_{MAX} = 25.5 \text{ mA}$ .
- When  $V_{CC}$  is in the range from 3.3 V to 5.5 V, and the Max\_Current\_Option (bit) = 1,  $I_{MAX} = 35 \text{ mA}$ .

### 8.3.4 Automatic Power-Save Mode

When all the LED outputs are inactive, the LP503x device is able to enter power-save mode automatically, thus lowering idle-current consumption down to 12  $\mu\text{A}$  (maximum). Automatic power-save mode is enabled when register bit Power\_Save\_EN = 1 (default) and all the LEDs are off for a duration of >30 ms. Almost all analog blocks are powered down in power-save mode. If any I<sup>2</sup>C command to the device occurs, the LP503x device returns to NORMAL mode.

### 8.3.5 Protection Features

#### 8.3.5.1 Thermal Shutdown

The LP503x device implements a thermal shutdown mechanism to protect the device from damage due to overheating. When the junction temperature rises to 160°C (typical), the device switches into shutdown mode. The LP503x device releases thermal shutdown when the junction temperature of the device is reduced to 145°C (typical).

#### 8.3.5.2 UVLO

The LP503x device has an internal comparator that monitors the voltage at  $V_{CC}$ . When  $V_{CC}$  is below  $V_{UVF}$ , reset is active and the LP503x device is in the INITIALIZATION state.

## 8.4 Device Functional Modes

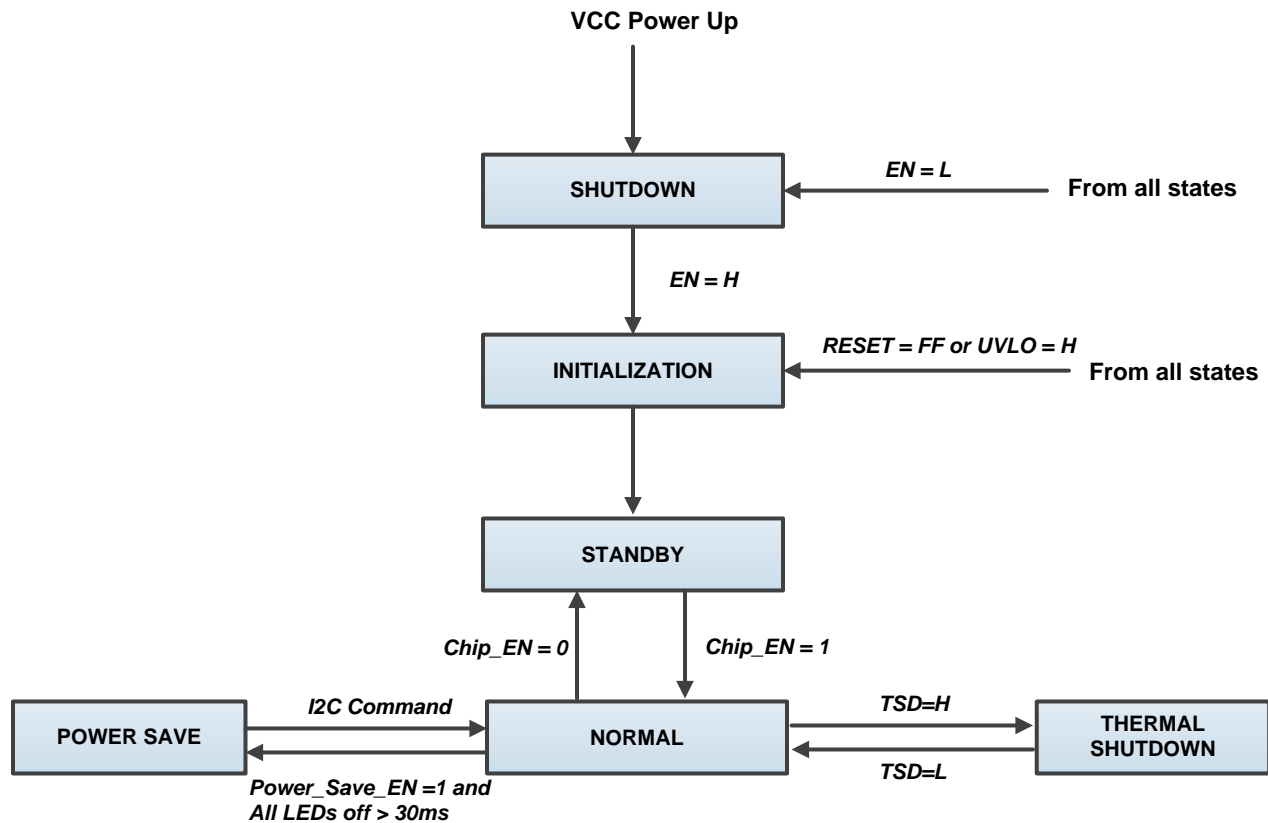


图 15. Functional Modes

- **INITIALIZATION:** The device enters into INITIALIZATION mode when EN = H. In this mode, all the registers are reset. Entry can also be from any state, if the RESET (register) = FFh or UVLO is active.
- **NORMAL:** The device enters the NORMAL mode when Chip\_EN (register) = 1.  $I_{CC}$  is 10 mA (typical).
- **POWER SAVE:** The device automatically enters the POWER SAVE mode when Power\_Save\_EN (register) = 1 and all the LEDs are off for a duration of >30 ms. In POWER SAVE mode, analog blocks are disabled to minimize power consumption, but the registers retain the data and keep it available via I<sup>2</sup>C.  $I_{CC}$  is 12  $\mu$ A (maximum). In case of any I<sup>2</sup>C command to this device, it goes back to the NORMAL mode.
- **SHUTDOWN:** The device enters into SHUTDOWN mode from all states on V<sub>CC</sub> power up or when EN = L.  $I_{CC}$  is < 1  $\mu$ A (max).
- **STANDBY:** The device enters the STANDBY mode when Chip\_EN (register bit) = 0. In this mode, all the OUTx are shut down, but the registers retain the data and keep it available via I<sup>2</sup>C. STANDBY is the low-power-consumption mode, when all circuit functions are disabled.  $I_{CC}$  is 10  $\mu$ A (maximum).
- **THERMAL SHUTDOWN:** The device automatically enters the THERMAL SHUTDOWN mode when the junction temperature exceeds 160°C (typical). In this mode, all the OUTx outputs are shut down. If the junction temperature decreases below 145°C (typical), the device returns to the NORMAL mode.

## 8.5 Programming

### 8.5.1 I<sup>2</sup>C Interface

The I<sup>2</sup>C-compatible two-wire serial interface provides access to the programmable functions and registers on the device. This protocol uses a two-wire interface for bidirectional communications between the devices connected to the bus. The two interface lines are the serial data line (SDA) and the serial clock line (SCL). Every device on the bus is assigned a unique address and acts as either a master or a slave depending on whether it generates or receives the serial clock, SCL. The SCL and SDA lines should each have a pullup resistor placed somewhere on the line and remain HIGH even when the bus is idle.

#### 8.5.1.1 Data Validity

The data on SDA line must be stable during the HIGH period of the clock signal (SCL). In other words, the state of the data line can only be changed when the clock signal is LOW.

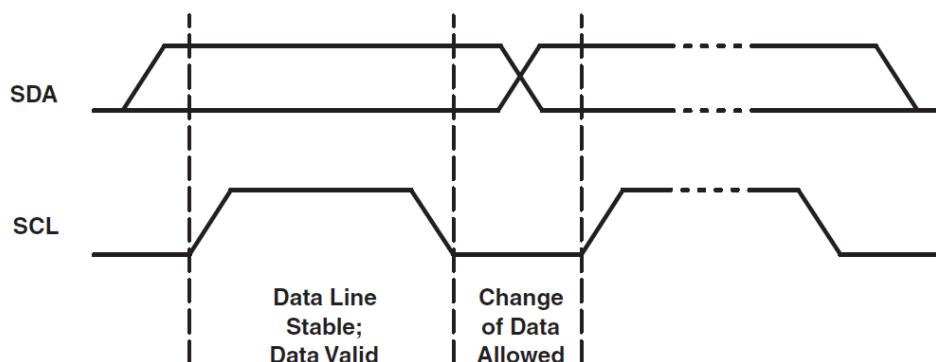


图 16. Data Validity

#### 8.5.1.2 Start and Stop Conditions

START and STOP conditions classify the beginning and the end of the data transfer session. A START condition is defined as the SDA signal transitioning from HIGH to LOW while the SCL line is HIGH. A STOP condition is defined as the SDA transitioning from LOW to HIGH while SCL is HIGH. The bus master always generates START and STOP conditions. The bus is considered to be busy after a START condition and free after a STOP condition. During data transmission, the bus master can generate repeated START conditions. First START and repeated START conditions are functionally equivalent.

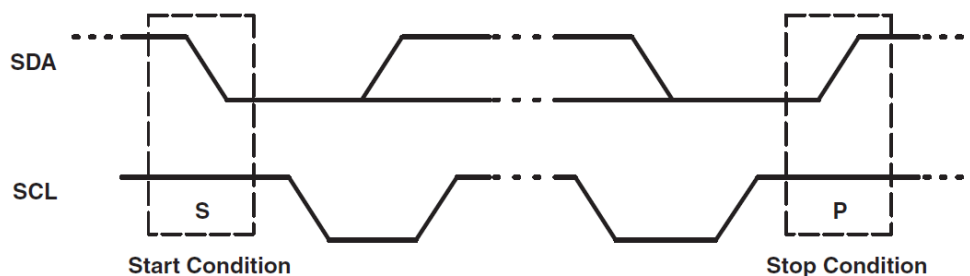


图 17. Start and Stop Conditions

#### 8.5.1.3 Transferring Data

Every byte put on the SDA line must be eight bits long, with the most-significant bit (MSB) being transferred first. Each byte of data must be followed by an acknowledge bit. The acknowledge-related clock pulse is generated by the master. The master releases the SDA line (HIGH) during the acknowledge clock pulse. The device pulls down the SDA line during the 9th clock pulse, signifying an acknowledge. The device generates an acknowledge after each byte has been received.

## Programming (接下页)

There is one exception to the acknowledge-after-every-byte rule. When the master is the receiver, it must indicate to the transmitter an end of data by not acknowledging (negative acknowledge) the last byte clocked out of the slave. This negative acknowledge still includes the acknowledge clock pulse (generated by the master), but the SDA line is not pulled down.

After the START condition, the bus master sends a chip address. This address is seven bits long followed by an eighth bit, which is a data direction bit (READ or WRITE). For the eighth bit, a 0 indicates a WRITE, and a 1 indicates a READ. The second byte selects the register to which the data is written. The third byte contains data to write to the selected register.

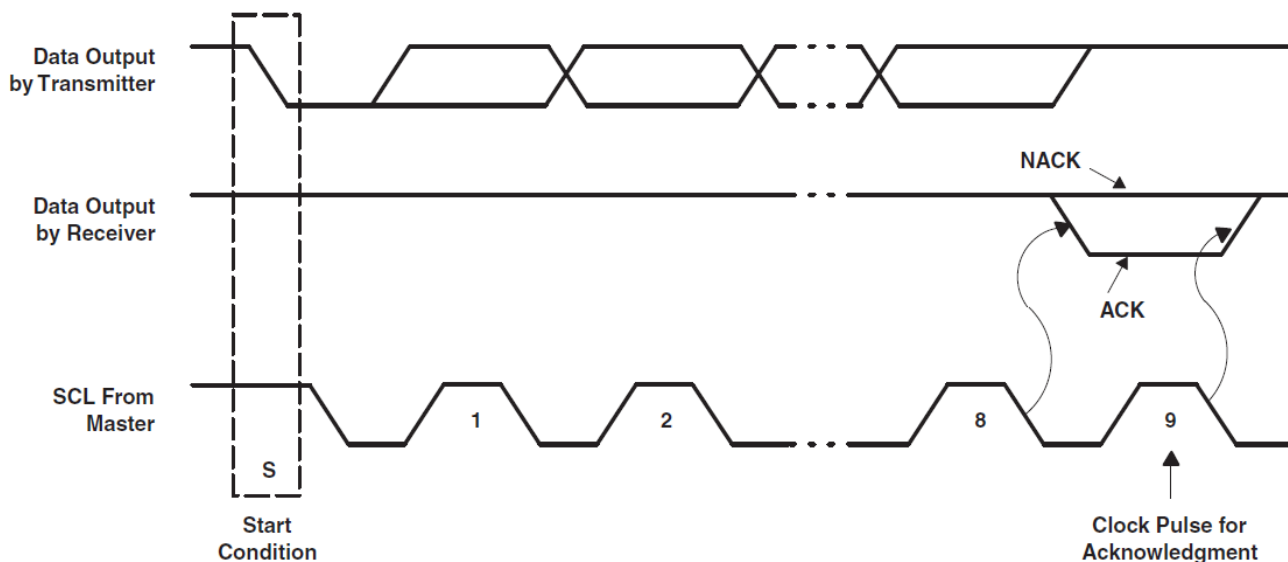


图 18. Acknowledge and Not Acknowledge on I<sup>2</sup>C Bus

### 8.5.1.4 I<sup>2</sup>C Slave Addressing

The device slave address is defined by connecting GND or VCC to the ADDR0 and ADDR1 pins. A total of four independent slave addresses can be realized by combinations when GND or VCC is connected to the ADDR0 and ADDR1 pins (see 表 2 and 表 3).

The device responds to a broadcast slave address regardless of the setting of the ADDR0 and ADDR1 pins. Global writes to the broadcast address can be used for configuring all devices simultaneously. The device supports global read using a broadcast address; however, the data read is only valid if all devices on the I<sup>2</sup>C bus contain the same value in the addressed register.

表 2. Slave-Address Combinations

ADDR1	ADDR0	SLAVE ADDRESS	
		INDEPENDENT	BROADCAST
GND	GND	011 0000	001 1100
GND	VCC	011 0001	
VCC	GND	011 0010	
VCC	VCC	011 0011	

表 3. Chip Address

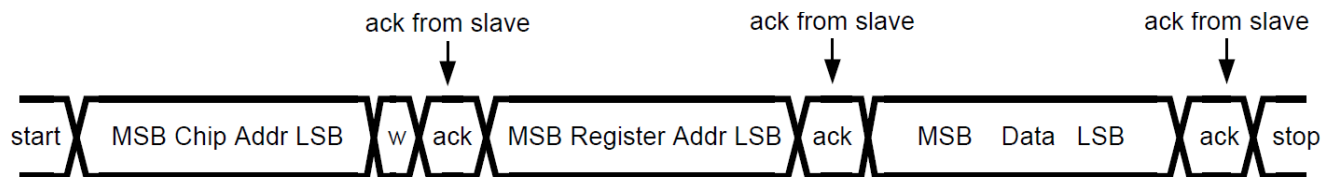
	SLAVE ADDRESS							R/W
	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
Independent	0	1	1	0	0	ADDR1	ADDR0	1 or 0

**表 3. Chip Address (接下页)**

	SLAVE ADDRESS							R/ $\overline{W}$
	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
Broadcast	0	0	1	1	1	0	0	1 or 0

#### 8.5.1.5 Control-Register Write Cycle

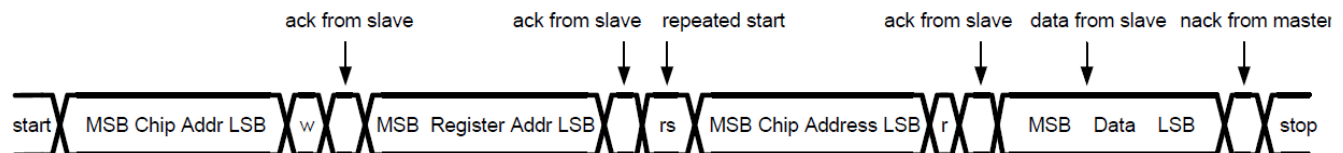
- The master device generates a start condition.
- The master device sends the slave address (7 bits) and the data direction bit ( $R/\overline{W} = 0$ ).
- The slave device sends an acknowledge signal if the slave address is correct.
- The master device sends the control register address (8 bits).
- The slave device sends an acknowledge signal.
- The master device sends the data byte to be written to the addressed register.
- The slave device sends an acknowledge signal.
- If the master device sends further data bytes, the control register address of the slave is incremented by 1 after the acknowledge signal. To reduce program load time, the device supports address auto incrementation. The register address is incremented after each 8 data bits.
- The write cycle ends when the master device creates a stop condition.



**图 19. Write Cycle**

#### 8.5.1.6 Control-Register Read Cycle

- The master device generates a start condition.
- The master device sends the slave address (7 bits) and the data direction bit ( $R/\overline{W} = 0$ ).
- The slave device sends an acknowledge signal if the slave address is correct.
- The master device sends the control register address (8 bits).
- The slave device sends an acknowledge signal.
- The master device generates a repeated-start condition.
- The master device sends the slave address (7 bits) and the data direction bit ( $R/\overline{W} = 1$ ).
- The slave device sends an acknowledge signal if the slave address is correct.
- The slave device sends the data byte from the addressed register.
- If the master device sends an acknowledge signal, the control-register address is incremented by 1. The slave device sends the data byte from the addressed register. To reduce program load time, the device supports address auto incrementation. The register address is incremented after each 8 data bits.
- The read cycle ends when the master device does not generate an acknowledge signal after a data byte and generates a stop condition.



**图 20. Read Cycle**

#### **8.5.1.7 Auto-Increment Feature**

The auto-increment feature allows writing or reading several consecutive registers within one transmission. For example, when an 8-bit word is sent to the device, the internal address index counter is incremented by 1, and the next register is written. The auto-increment feature is enabled by default and can be disabled by setting the Auto\_Incr\_EN bit = 0 in the DEVICE\_CONFIG1 register. The auto-increment feature is applied for the full register address from 0h to FFh.

## 8.6 Register Maps

表 4 lists the memory-mapped registers of the device.

**表 4. Register Maps**

REGISTER NAME	ADDR	TYPE	D7	D6	D5	D4	D3	D2	D1	D0	DEF AULT
DEVICE_CONFIG0	00h	R/W	RESERVED	Chip_EN	RESERVED						00h
DEVICE_CONFIG1	01h	R/W	RESERVED		Log_Scale_EN	Power_Save_EN	Auto_Incr_EN	PWM_Dithering_EN	Max_Current_Option	LED_Global Off	3Ch
LED_CONFIG0	02h	R/W	LED7_Bank_EN	LED6_Bank_EN	LED5_Bank_EN	LED4_Bank_EN	LED3_Bank_EN	LED2_Bank_EN	LED1_Bank_EN	LED0_Bank_EN	00h
LED_CONFIG1	03h	R/W	RESERVED				LED11_Bank_EN	LED10_Bank_EN	LED9_Bank_EN	LED8_Bank_EN	00h
BANK_BRIGHTNESS	04h	R/W	Bank_Brightness								FFh
BANK_A_COLOR	05h	R/W	Bank_A_Color								00h
BANK_B_COLOR	06h	R/W	Bank_B_Color								00h
BANK_C_COLOR	07h	R/W	Bank_C_Color								00h
LED0_BRIGHTNESS	08h	R/W	LED0_Brightness								FFh
LED1_BRIGHTNESS	09h	R/W	LED1_Brightness								FFh
LED2_BRIGHTNESS	0Ah	R/W	LED2_Brightness								FFh
LED3_BRIGHTNESS	0Bh	R/W	LED3_Brightness								FFh
LED4_BRIGHTNESS	0Ch	R/W	LED4_Brightness								FFh
LED5_BRIGHTNESS	0Dh	R/W	LED5_Brightness								FFh
LED6_BRIGHTNESS	0Eh	R/W	LED6_Brightness								FFh
LED7_BRIGHTNESS	0Fh	R/W	LED7_Brightness								FFh
LED8_BRIGHTNESS	10h	R/W	LED8_Brightness								FFh
LED9_BRIGHTNESS	11h	R/W	LED9_Brightness								FFh

## Register Maps (接下页)

表 4. Register Maps (接下页)

REGISTER NAME	ADDR	TYPE	D7	D6	D5	D4	D3	D2	D1	D0	DEF AULT
LED10_BRIGHTNESS	12h	R $\overline{W}$	LED10_Brightness								FFh
LED11_BRIGHTNESS	13h	R $\overline{W}$	LED11_Brightness								FFh
OUT0_COLOR	14h	R $\overline{W}$	OUT0_Color								00h
OUT1_COLOR	15h	R $\overline{W}$	OUT1_Color								00h
OUT2_COLOR	16h	R $\overline{W}$	OUT2_Color								00h
OUT3_COLOR	17h	R $\overline{W}$	OUT3_Color								00h
OUT4_COLOR	18h	R $\overline{W}$	OUT4_Color								00h
OUT5_COLOR	19h	R $\overline{W}$	OUT5_Color								00h
OUT6_COLOR	1Ah	R $\overline{W}$	OUT6_Color								00h
OUT7_COLOR	1Bh	R $\overline{W}$	OUT7_Color								00h
OUT8_COLOR	1Ch	R $\overline{W}$	OUT8_Color								00h
OUT9_COLOR	1Dh	R $\overline{W}$	OUT9_Color								00h
OUT10_COLOR	1Eh	R $\overline{W}$	OUT10_Color								00h
OUT11_COLOR	1Fh	R $\overline{W}$	OUT11_Color								00h
OUT12_COLOR	20h	R $\overline{W}$	OUT12_Color								00h
OUT13_COLOR	21h	R $\overline{W}$	OUT13_Color								00h
OUT14_COLOR	22h	R $\overline{W}$	OUT14_Color								00h
OUT15_COLOR	23h	R $\overline{W}$	OUT15_Color								00h
OUT16_COLOR	24h	R $\overline{W}$	OUT16_Color								00h
OUT17_COLOR	25h	R $\overline{W}$	OUT17_Color								00h
OUT18_COLOR	26h	R $\overline{W}$	OUT18_Color								00h
OUT19_COLOR	27h	R $\overline{W}$	OUT19_Color								00h
OUT20_COLOR	28h	R $\overline{W}$	OUT20_Color								00h
OUT21_COLOR	29h	R $\overline{W}$	OUT21_Color								00h
OUT22_COLOR	2Ah	R $\overline{W}$	OUT22_Color								00h
OUT23_COLOR	2Bh	R $\overline{W}$	OUT23_Color								00h
OUT24_COLOR	2Ch	R $\overline{W}$	OUT24_Color								00h
OUT25_COLOR	2Dh	R $\overline{W}$	OUT25_Color								00h
OUT26_COLOR	2Eh	R $\overline{W}$	OUT26_Color								00h
OUT27_COLOR	2Fh	R $\overline{W}$	OUT27_Color								00h

**LP5030, LP5036**

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**Register Maps (接下页)**
**表 4. Register Maps (接下页)**

REGISTER NAME	ADDR	TYPE	D7	D6	D5	D4	D3	D2	D1	D0	DEF AULT
OUT28_COLOR	30h	R/ $\overline{W}$	OUT28_Color								00h
OUT29_COLOR	31h	R/ $\overline{W}$	OUT29_Color								00h
OUT30_COLOR	32h	R/ $\overline{W}$	OUT30_Color								00h
OUT31_COLOR	33h	R/ $\overline{W}$	OUT31_Color								00h
OUT32_COLOR	34h	R/ $\overline{W}$	OUT32_Color								00h
OUT33_COLOR	35h	R/ $\overline{W}$	OUT33_Color								00h
OUT34_COLOR	36h	R/ $\overline{W}$	OUT34_Color								00h
OUT35_COLOR	37h	R/ $\overline{W}$	OUT35_Color								00h
RESET	38h	W	Reset								00h

**表 5. Access Type Codes**

ACCESS TYPE	CODE	DESCRIPTION
<b>Read Type</b>		
R	R	Read
<b>Write Type</b>		
W	W	Write
<b>Reset or Default Value</b>		
-n		Value after reset or the default value

### 8.6.1 DEVICE\_CONFIG0 (Address = 0h) [reset = 0h]

DEVICE\_CONFIG0 is shown in 图 21 and described in 表 6.

Return to 表 4.

**图 21. DEVICE\_CONFIG0 Register**

7	6	5	4	3	2	1	0
RESERVED	Chip_EN	RESERVED					
R/W-0h	R/W-0h	R/W-0h					

**表 6. DEVICE\_CONFIG0 Register Field Descriptions**

Bit	Field	Type	Reset	Description
7	RESERVED	R/W	0h	Reserved
6	Chip_EN	R/W	0h	0 = LP503x not enabled 1 = LP503x enabled
5–0	RESERVED	R/W	0h	Reserved

### 8.6.2 DEVICE\_CONFIG1 (Address = 1h) [reset = 3Ch]

DEVICE\_CONFIG1 is shown in 图 22 and described in 表 7.

Return to 表 4.

**图 22. DEVICE\_CONFIG1 Register**

7	6	5	4	3	2	1	0
RESERVED	Log_Scale_EN	Power_Save_EN	Auto_Incr_EN	PWM_Dithering_EN	Max_Current_Option	LED_Global Off	
R/W-0h	R/W-1h	R/W-1h	R/W-1h	R/W-1h	R/W-1h	R/W-0h	R/W-0h

**表 7. DEVICE\_CONFIG1 Register Field Descriptions**

Bit	Field	Type	Reset	Description
7–6	RESERVED	R/W	0h	Reserved
5	Log_Scale_EN	R/W	1h	0 = Linear scale dimming curve enabled 1 = Logarithmic scale dimming curve enabled
4	Power_Save_EN	R/W	1h	0 = Automatic power-saving mode not enabled 1 = Automatic power-saving mode enabled
3	Auto_Incr_EN	R/W	1h	0 = Automatic increment mode not enabled 1 = Automatic increment mode enabled
2	PWM_Dithering_EN	R/W	1h	0 = PWM dithering mode not enabled 1 = PWM dithering mode enabled
1	Max_Current_Option	R/W	0h	0 = Output maximum current I <sub>MAX</sub> = 25.5 mA. 1 = Output maximum current I <sub>MAX</sub> = 35 mA.

**表 7. DEVICE\_CONFIG1 Register Field Descriptions (接下页)**

Bit	Field	Type	Reset	Description
0	LED_Global Off	R/W	0h	0 = Normal operation 1 = Shut down all LEDs

### 8.6.3 LED\_CONFIG0 (Address = 2h) [reset = 00h]

LED\_CONFIG0 is shown in 图 23 and described in 表 8.

Return to 表 4.

**图 23. LED\_CONFIG0 Register**

7	6	5	4	3	2	1	0
LED7_Bank_EN	LED6_Bank_EN	LED5_Bank_EN	LED4_Bank_EN	LED3_Bank_EN	LED2_Bank_EN	LED1_Bank_EN	LED0_Bank_EN
R/W-0h	R/W-0h	R/W-0h	R/W-0h	R/W-0h	R/W-0h	R/W-0h	R/W-0h

**表 8. LED\_CONFIG0 Register Field Descriptions**

Bit	Field	Type	Reset	Description
7	LED7_Bank_EN	R/W	0h	0 = LED7 independent control mode enabled 1 = LED7 bank control mode enabled
6	LED6_Bank_EN	R/W	0h	0 = LED6 independent control mode enabled 1 = LED6 bank control mode enabled
5	LED5_Bank_EN	R/W	0h	0 = LED5 independent control mode enabled 1 = LED5 bank control mode enabled
4	LED4_Bank_EN	R/W	0h	0 = LED4 independent control mode enabled 1 = LED4 bank control mode enabled
3	LED3_Bank_EN	R/W	0h	0 = LED3 Independent control mode enabled 1 = LED3 bank control mode enabled
2	LED2_Bank_EN	R/W	0h	0 = LED2 independent control mode enabled 1 = LED2 bank control mode enabled
1	LED1_Bank_EN	R/W	0h	0 = LED1 independent control mode enabled 1 = LED1 bank control mode enabled
0	LED0_Bank_EN	R/W	0h	0 = LED0 independent control mode enabled 1 = LED0 bank control mode enabled

### 8.6.4 LED\_CONFIG1 (Address = 3h) [reset = 00h]

LED\_CONFIG1 is shown in 图 23 and described in 表 8.

Return to 表 4.

**图 24. LED\_CONFIG1 Register**

7	6	5	4	3	2	1	0
RESERVED				LED11_Bank_EN	LED10_Bank_EN	LED9_Bank_EN	LED8_Bank_EN
R/W-0h				R/W-0h	R/W-0h	R/W-0h	R/W-0h

**表 9. LED\_CONFIG1 Register Field Descriptions**

Bit	Field	Type	Reset	Description
4–7	RESERVED	R/W	0h	Reserved
3	LED11_Bank_EN	R/W	0h	0 = LED11 Independent control mode enabled 1 =LED11 bank control mode enabled

**表 9. LED\_CONFIG1 Register Field Descriptions (接下页)**

Bit	Field	Type	Reset	Description
2	LED10_Bank_EN	R/W	0h	0 = LED10 independent control mode enabled 1 = LED10 bank control mode enabled
1	LED9_Bank_EN	R/W	0h	0 = LED9 independent control mode enabled 1 = LED9 bank control mode enabled
0	LED8_Bank_EN	R/W	0h	0 = LED8 independent control mode enabled 1 = LED8 bank control mode enabled

#### 8.6.5 BANK\_BRIGHTNESS (Address = 4h) [reset = FFh]

BANK\_BRIGHTNESS is shown in 图 25 and described in 表 10.

Return to 表 4.

**图 25. BANK\_BRIGHTNESS Register**

7	6	5	4	3	2	1	0
BANK_BRIGHTNESS							
R/W-FFh							

**表 10. BANK\_BRIGHTNESS Register Field Descriptions**

Bit	Field	Type	Reset	Description
7–0	BANK_BRIGHTNESS	R/W	FFh	00h = 0% of full intensity ... 80h = 50% of full ... FFh = 100 % of full intensity

#### 8.6.6 BANK\_A\_COLOR (Address = 5h) [reset = 00h]

BANK\_A\_COLOR is shown in 图 26 and described in 表 11.

Return to 表 4.

**图 26. BANK\_A\_COLOR Register**

7	6	5	4	3	2	1	0
BANK_A_COLOR							
R/W-0h							

**表 11. BANK\_A\_COLOR Register Field Descriptions**

Bit	Field	Type	Reset	Description
7–0	BANK_A_COLOR	R/W	0h	00h = The color mixing percentage is 0%. ... 80h = The color mixing percentage is 50%. ... FFh = The color mixing percentage is 100%.

#### 8.6.7 BANK\_B\_COLOR (Address = 6h) [reset = 00h]

BANK\_B\_COLOR is shown in 图 27 and described in 表 12.

Return to 表 4.

**图 27. BANK\_B\_COLOR Register**

7	6	5	4	3	2	1	0
BANK_B_COLOR							
R/W-0h							

**表 12. BANK\_B\_COLOR Register Field Descriptions**

Bit	Field	Type	Reset	Description
7–0	BANK_B_COLOR	R/W	0h	00h = The color mixing percentage is 0%. ... 80h = The color mixing percentage is 50%. ... FFh = The color mixing percentage is 100%.

### 8.6.8 BANK\_C\_COLOR (Address = 7h) [reset = 00h]

BANK\_C\_COLOR is shown in 图 28 and described in 表 13.

Return to 表 4.

**图 28. BANK\_C\_COLOR Register**

7	6	5	4	3	2	1	0
BANK_C_COLOR							
R/W-0h							

**表 13. BANK\_C\_COLOR Register Field Descriptions**

Bit	Field	Type	Reset	Description
7–0	BANK_C_COLOR	R/W	0h	00h = The color mixing percentage is 0%. ... 80h = The color mixing percentage is 50%. ... FFh = The color mixing percentage is 100%.

### 8.6.9 LED0\_BRIGHTNESS (Address = 8h) [reset = FFh]

LED0\_BRIGHTNESS is shown in 图 29 and described in 表 14.

Return to 表 4.

**图 29. LED0\_BRIGHTNESS Register**

7	6	5	4	3	2	1	0
LED0_BRIGHTNESS							
R/W-FFh							

**表 14. LED0\_BRIGHTNESS Register Field Descriptions**

Bit	Field	Type	Reset	Description
7–0	LED0_BRIGHTNESS	R/W	FFh	00h = 0% of full intensity ... 80h = 50% of full intensity ... FFh = 100 % of full intensity

### 8.6.10 LED1\_BRIGHTNESS (Address = 9h) [reset = FFh]

LED1\_BRIGHTNESS is shown in 图 30 and described in 表 15.

Return to 表 4.

**图 30. LED1\_BRIGHTNESS Register**

7	6	5	4	3	2	1	0
LED1_BRIGHTNESS							
R/W-FFh							

**表 15. LED1\_BRIGHTNESS Register Field Descriptions**

Bit	Field	Type	Reset	Description
7–0	LED1_BRIGHTNESS	R/W	FFh	00h = 0% of full intensity ... 80h = 50% of full intensity ... FFh = 100 % of full intensity

### 8.6.11 LED2\_BRIGHTNESS (Address = 0Ah) [reset = FFh]

LED2\_BRIGHTNESS is shown in 图 31 and described in 表 16.

Return to 表 4.

**图 31. LED2\_BRIGHTNESS Register**

7	6	5	4	3	2	1	0
LED2_BRIGHTNESS							
R/W-FFh							

**表 16. LED2\_BRIGHTNESS Register Field Descriptions**

Bit	Field	Type	Reset	Description
7–0	LED2_BRIGHTNESS	R/W	FFh	00h = 0% of full intensity ... 80h = 50% of full intensity ... FFh = 100 % of full intensity

### 8.6.12 LED3\_BRIGHTNESS (Address = 0Bh) [reset = FFh]

LED3\_BRIGHTNESS is shown in 图 32 and described in 表 17.

Return to 表 4.

**图 32. LED3\_BRIGHTNESS Register**

7	6	5	4	3	2	1	0
LED3_BRIGHTNESS							
R/W-FFh							

**表 17. LED3\_BRIGHTNESS Register Field Descriptions**

Bit	Field	Type	Reset	Description
7–0	LED3_BRIGHTNESS	R/W	FFh	00h = 0% of full intensity ... 80h = 50% of full intensity ... FFh = 100 % of full intensity

**8.6.13 LED4\_BRIGHTNESS (Address = 0Ch) [reset = FFh]**

LED4\_BRIGHTNESS is shown in 图 33 and described in 表 18.

Return to 表 4.

**图 33. LED4\_BRIGHTNESS Register**

7	6	5	4	3	2	1	0
LED4_BRIGHTNESS							
R/W-FFh							

**表 18. LED4\_BRIGHTNESS Register Field Descriptions**

Bit	Field	Type	Reset	Description
7–0	LED4_BRIGHTNESS	R/W	FFh	00h = 0% of full intensity ... 80h = 50% of full intensity ... FFh = 100 % of full intensity

**8.6.14 LED5\_BRIGHTNESS (Address = 0Dh) [reset = FFh]**

LED5\_BRIGHTNESS is shown in 图 34 and described in 表 19.

Return to 表 4.

**图 34. LED5\_BRIGHTNESS Register**

7	6	5	4	3	2	1	0
LED5_BRIGHTNESS							
R/W-FFh							

**表 19. LED5\_BRIGHTNESS Register Field Descriptions**

Bit	Field	Type	Reset	Description
7–0	LED5_BRIGHTNESS	R/W	FFh	00h = 0% of full intensity ... 80h = 50% of full intensity ... FFh = 100 % of full intensity

**8.6.15 LED6\_BRIGHTNESS (Address = 0Eh) [reset = FFh]**

LED6\_BRIGHTNESS is shown in 图 35 and described in 表 20.

Return to 表 4.

**图 35. LED6\_BRIGHTNESS Register**

7	6	5	4	3	2	1	0
LED6_BRIGHTNESS							
R/W-FFh							

**表 20. LED6\_BRIGHTNESS Register Field Descriptions**

Bit	Field	Type	Reset	Description
7–0	LED6_BRIGHTNESS	R/W	FFh	00h = 0% of full intensity ... 80h = 50% of full intensity ... FFh = 100 % of full intensity

#### 8.6.16 LED7\_BRIGHTNESS (Address = 0Fh) [reset = FFh]

LED7\_BRIGHTNESS is shown in 图 36 and described in 表 21.

Return to 表 4.

**图 36. LED7\_BRIGHTNESS Register**

7	6	5	4	3	2	1	0
LED7_BRIGHTNESS							
R/W-FFh							

**表 21. LED7\_BRIGHTNESS Register Field Descriptions**

Bit	Field	Type	Reset	Description
7–0	LED7_BRIGHTNESS	R/W	FFh	00h = 0% of full intensity ... 80h = 50% of full intensity ... FFh = 100 % of full intensity

#### 8.6.17 LED8\_BRIGHTNESS (Address = 10h) [reset = FFh]

LED8\_BRIGHTNESS is shown in 图 37 and described in 表 22.

Return to 表 4.

**图 37. LED8\_BRIGHTNESS Register**

7	6	5	4	3	2	1	0
LED8_BRIGHTNESS							
R/W-FFh							

**表 22. LED8\_BRIGHTNESS Register Field Descriptions**

Bit	Field	Type	Reset	Description
7–0	LED8_BRIGHTNESS	R/W	FFh	00h = 0% of full intensity ... 80h = 50% of full intensity ... FFh = 100 % of full intensity

### 8.6.18 LED9\_BRIGHTNESS (Address = 11h) [reset = FFh]

LED9\_BRIGHTNESS is shown in 图 38 and described in 表 23.

Return to 表 4.

**图 38. LED9\_BRIGHTNESS Register**

7	6	5	4	3	2	1	0
LED9_BRIGHTNESS							
R/W-FFh							

**表 23. LED9\_BRIGHTNESS Register Field Descriptions**

Bit	Field	Type	Reset	Description
7–0	LED9_BRIGHTNESS	R/W	FFh	00h = 0% of full intensity ... 80h = 50% of full intensity ... FFh = 100 % of full intensity

### 8.6.19 LED10\_BRIGHTNESS (Address = 12h) [reset = FFh]

LED10\_BRIGHTNESS is shown in 图 39 and described in 表 24.

Return to 表 4.

**图 39. LED10\_BRIGHTNESS Register**

7	6	5	4	3	2	1	0
LED10_BRIGHTNESS							
R/W-FFh							

**表 24. LED10\_BRIGHTNESS Register Field Descriptions**

Bit	Field	Type	Reset	Description
7–0	LED10_BRIGHTNESS	R/W	FFh	00h = 0% of full intensity ... 80h = 50% of full intensity ... FFh = 100 % of full intensity

### 8.6.20 LED11\_BRIGHTNESS (Address = 13h) [reset = FFh]

LED11\_BRIGHTNESS is shown in 图 40 and described in 表 25.

Return to 表 4.

**图 40. LED11\_BRIGHTNESS Register**

7	6	5	4	3	2	1	0
LED11_BRIGHTNESS							
R/W-FFh							

**表 25. LED11\_BRIGHTNESS Register Field Descriptions**

Bit	Field	Type	Reset	Description
7–0	LED11_BRIGHTNESS	R/W	FFh	00h = 0% of full intensity ... 80h = 50% of full intensity ... FFh = 100 % of full intensity

#### 8.6.21 OUT0\_COLOR (Address = 14h) [reset = 00h]

OUT0\_COLOR is shown in 图 41 and described in 表 26.

Return to 表 4.

**图 41. OUT0\_COLOR Register**

7	6	5	4	3	2	1	0
OUT0_COLOR							
R/W-00h							

**表 26. OUT0\_COLOR Register Field Descriptions**

Bit	Field	Type	Reset	Description
7–0	OUT0_COLOR	R/W	00h	00h = The color mixing percentage is 0%. ... 80h = The color mixing percentage is 50%. ... FFh = The color mixing percentage is 100%.

#### 8.6.22 OUT1\_COLOR (Address = 15h) [reset = 00h]

OUT1\_COLOR is shown in 图 42 and described in 表 27.

Return to 表 4.

**图 42. OUT1\_COLOR Register**

7	6	5	4	3	2	1	0
OUT1_COLOR							
R/W-00h							

**表 27. OUT1\_COLOR Register Field Descriptions**

Bit	Field	Type	Reset	Description
7–0	OUT1_COLOR	R/W	00h	00h = The color mixing percentage is 0%. ... 80h = The color mixing percentage is 50%. ... FFh = The color mixing percentage is 100%.

#### 8.6.23 OUT2\_COLOR (Address = 16h) [reset = 00h]

OUT2\_COLOR is shown in 图 43 and described in 表 28.

Return to 表 4.

**图 43. OUT2\_COLOR Register**

7	6	5	4	3	2	1	0
OUT2_COLOR							
R/W-00h							

**表 28. OUT2\_COLOR Register Field Descriptions**

Bit	Field	Type	Reset	Description
7–0	OUT2_COLOR	R/W	00h	00h = The color mixing percentage is 0%. ... 80h = The color mixing percentage is 50%. ... FFh = The color mixing percentage is 100%.

#### 8.6.24 OUT3\_COLOR (Address = 17h) [reset = 00h]

OUT3\_COLOR is shown in 图 44 and described in 表 29.

Return to 表 4.

**图 44. OUT3\_COLOR Register**

7	6	5	4	3	2	1	0
OUT3_COLOR							
R/W-00h							

**表 29. OUT3\_COLOR Register Field Descriptions**

Bit	Field	Type	Reset	Description
7–0	OUT3_COLOR	R/W	00h	00h = The color mixing percentage is 0%. ... 80h = The color mixing percentage is 50%. ... FFh = The color mixing percentage is 100%.

#### 8.6.25 OUT4\_COLOR (Address = 18h) [reset = 00h]

OUT4\_COLOR is shown in 图 45 and described in 表 30.

Return to 表 4.

**图 45. OUT4\_COLOR Register**

7	6	5	4	3	2	1	0
OUT4_COLOR							
R/W-00h							

**表 30. OUT4\_COLOR Register Field Descriptions**

Bit	Field	Type	Reset	Description
7–0	OUT4_COLOR	R/W	00h	00h = The color mixing percentage is 0%. ... 80h = The color mixing percentage is 50%. ... FFh = The color mixing percentage is 100%.

### 8.6.26 OUT5\_COLOR (Address = 19h) [reset = 00h]

OUT5\_COLOR is shown in 图 46 and described in 表 31.

Return to 表 4.

**图 46. OUT5\_COLOR Register**

7	6	5	4	3	2	1	0
OUT5_COLOR							
R/W-00h							

**表 31. OUT5\_COLOR Register Field Descriptions**

Bit	Field	Type	Reset	Description
7–0	OUT5_COLOR	R/W	00h	00h = The color mixing percentage is 0%. ... 80h = The color mixing percentage is 50%. ... FFh = The color mixing percentage is 100%.

### 8.6.27 OUT6\_COLOR (Address = 1Ah) [reset = 00h]

OUT6\_COLOR is shown in 图 47 and described in 表 32.

Return to 表 4.

**图 47. OUT6\_COLOR Register**

7	6	5	4	3	2	1	0
OUT6_COLOR							
R/W-00h							

**表 32. OUT6\_COLOR Register Field Descriptions**

Bit	Field	Type	Reset	Description
7–0	OUT6_COLOR	R/W	00h	00h = The color mixing percentage is 0%. ... 80h = The color mixing percentage is 50%. ... FFh = The color mixing percentage is 100%.

### 8.6.28 OUT7\_COLOR (Address = 1Bh) [reset = 00h]

OUT7\_COLOR is shown in 图 48 and described in 表 33.

Return to 表 4.

**图 48. OUT7\_COLOR Register**

7	6	5	4	3	2	1	0
OUT7_COLOR							
R/W-00h							

**表 33. OUT7\_COLOR Register Field Descriptions**

Bit	Field	Type	Reset	Description
7–0	OUT7_COLOR	R/W	00h	00h = The color mixing percentage is 0%. ... 80h = The color mixing percentage is 50%. ... FFh = The color mixing percentage is 100%.

#### 8.6.29 OUT8\_COLOR (Address = 1Ch) [reset = 00h]

OUT8\_COLOR is shown in 图 49 and described in 表 34.

Return to 表 4.

**图 49. OUT8\_COLOR Register**

7	6	5	4	3	2	1	0
OUT8_COLOR							
R/W-00h							

**表 34. OUT8\_COLOR Register Field Descriptions**

Bit	Field	Type	Reset	Description
7–0	OUT8_COLOR	R/W	00h	00h = The color mixing percentage is 0%. ... 80h = The color mixing percentage is 50%. ... FFh = The color mixing percentage is 100%.

#### 8.6.30 OUT9\_COLOR (Address = 1Dh) [reset = 00h]

OUT9\_COLOR is shown in 图 50 and described in 表 35.

Return to 表 4.

**图 50. OUT9\_COLOR Register**

7	6	5	4	3	2	1	0
OUT9_COLOR							
R/W-00h							

**表 35. OUT9\_COLOR Register Field Descriptions**

Bit	Field	Type	Reset	Description
7–0	OUT9_COLOR	R/W	00h	00h = The color mixing percentage is 0%. ... 80h = The color mixing percentage is 50%. ... FFh = The color mixing percentage is 100%.

#### 8.6.31 OUT10\_COLOR (Address = 1Eh) [reset = 00h]

OUT10\_COLOR is shown in 图 51 and described in 表 36.

Return to 表 4.

**图 51. OUT10\_COLOR Register**

7	6	5	4	3	2	1	0
OUT10_COLOR							
R/W0-0h							

**表 36. OUT10\_COLOR Register Field Descriptions**

Bit	Field	Type	Reset	Description
7–0	OUT10_COLOR	R/W	00h	00h = The color mixing percentage is 0%. ... 80h = The color mixing percentage is 50%. ... FFh = The color mixing percentage is 100%.

### 8.6.32 OUT11\_COLOR (Address = 1Fh) [reset = 00h]

OUT11\_COLOR is shown in 图 52 and described in 表 37.

Return to 表 4.

**图 52. OUT11\_COLOR Register**

7	6	5	4	3	2	1	0
OUT11_COLOR							
R/W-00h							

**表 37. OUT11\_COLOR Register Field Descriptions**

Bit	Field	Type	Reset	Description
7–0	OUT11_COLOR	R/W	00h	00h = The color mixing percentage is 0%. ... 80h = The color mixing percentage is 50%. ... FFh = The color mixing percentage is 100%.

### 8.6.33 OUT12\_COLOR (Address = 20h) [reset = 00h]

OUT12\_COLOR is shown in 图 53 and described in 表 38.

Return to 表 4.

**图 53. OUT12\_COLOR Register**

7	6	5	4	3	2	1	0
OUT12_COLOR							
R/W-00h							

**表 38. OUT12\_COLOR Register Field Descriptions**

Bit	Field	Type	Reset	Description
7–0	OUT12_COLOR	R/W	00h	00h = The color mixing percentage is 0%. ... 80h = The color mixing percentage is 50%. ... FFh = The color mixing percentage is 100%.

### 8.6.34 OUT13\_COLOR (Address = 21h) [reset = 00h]

OUT13\_COLOR is shown in 图 54 and described in 表 39.

Return to 表 4.

图 54. OUT13\_COLOR Register

7	6	5	4	3	2	1	0
OUT13_COLOR							
R/W-00h							

表 39. OUT13\_COLOR Register Field Descriptions

Bit	Field	Type	Reset	Description
7–0	OUT13_COLOR	R/W	00h	00h = The color mixing percentage is 0%. ... 80h = The color mixing percentage is 50%. ... FFh = The color mixing percentage is 100%.

### 8.6.35 OUT14\_COLOR (Address = 22h) [reset = 00h]

OUT14\_COLOR is shown in 图 55 and described in 表 40.

Return to 表 4.

图 55. OUT14\_COLOR Register

7	6	5	4	3	2	1	0
OUT14_COLOR							
R/W-00h							

表 40. OUT14\_COLOR Register Field Descriptions

Bit	Field	Type	Reset	Description
7–0	OUT14_COLOR	R/W	00h	00h = The color mixing percentage is 0%. ... 80h = The color mixing percentage is 50%. ... FFh = The color mixing percentage is 100%.

### 8.6.36 OUT15\_COLOR (Address = 23h) [reset = 00h]

OUT15\_COLOR is shown in 图 56 and described in 表 41.

Return to 表 4.

图 56. OUT15\_COLOR Register

7	6	5	4	3	2	1	0
OUT15_COLOR							
R/W-00h							

**表 41. OUT15\_COLOR Register Field Descriptions**

Bit	Field	Type	Reset	Description
7–0	OUT15_COLOR	R/W	00h	00h = The color mixing percentage is 0%. ... 80h = The color mixing percentage is 50%. ... FFh = The color mixing percentage is 100%.

#### 8.6.37 OUT16\_COLOR (Address = 24h) [reset = 00h]

OUT16\_COLOR is shown in 图 57 and described in 表 42.

Return to 表 4.

**图 57. OUT16\_COLOR Register**

7	6	5	4	3	2	1	0
OUT16_COLOR							
R/W-00h							

**表 42. OUT16\_COLOR Register Field Descriptions**

Bit	Field	Type	Reset	Description
7–0	OUT16_COLOR	R/W	00h	00h = The color mixing percentage is 0%. ... 80h = The color mixing percentage is 50%. ... FFh = The color mixing percentage is 100%.

#### 8.6.38 OUT17\_COLOR (Address = 25h) [reset = 00h]

OUT17\_COLOR is shown in 图 58 and described in 表 43.

Return to 表 4.

**图 58. OUT17\_COLOR Register**

7	6	5	4	3	2	1	0
OUT17_COLOR							
R/W-00h							

**表 43. OUT17\_COLOR Register Field Descriptions**

Bit	Field	Type	Reset	Description
7–0	OUT17_COLOR	R/W	00h	00h = The color mixing percentage is 0%. ... 80h = The color mixing percentage is 50%. ... FFh = The color mixing percentage is 100%.

#### 8.6.39 OUT18\_COLOR (Address = 26h) [reset = 00h]

OUT18\_COLOR is shown in 图 59 and described in 表 44.

Return to 表 4.

**图 59. OUT18\_COLOR Register**

7	6	5	4	3	2	1	0
OUT18_COLOR							
R/W-00h							

**表 44. OUT18\_COLOR Register Field Descriptions**

Bit	Field	Type	Reset	Description
7–0	OUT18_COLOR	R/W	00h	00h = The color mixing percentage is 0%. ... 80h = The color mixing percentage is 50%. ... FFh = The color mixing percentage is 100%.

#### 8.6.40 OUT19\_COLOR (Address = 27h) [reset = 00h]

OUT19\_COLOR is shown in 图 60 and described in 表 45.

Return to 表 4.

**图 60. OUT19\_COLOR Register**

7	6	5	4	3	2	1	0
OUT19_COLOR							
R/W-00h							

**表 45. OUT19\_COLOR Register Field Descriptions**

Bit	Field	Type	Reset	Description
7–0	OUT19_COLOR	R/W	00h	00h = The color mixing percentage is 0%. ... 80h = The color mixing percentage is 50%. ... FFh = The color mixing percentage is 100%.

#### 8.6.41 OUT20\_COLOR (Address = 28h) [reset = 00h]

OUT20\_COLOR is shown in 图 61 and described in 表 46.

Return to 表 4.

**图 61. OUT20\_COLOR Register**

7	6	5	4	3	2	1	0
OUT20_COLOR							
R/W-00h							

**表 46. OUT20\_COLOR Register Field Descriptions**

Bit	Field	Type	Reset	Description
7–0	OUT20_COLOR	R/W	00h	00h = The color mixing percentage is 0%. ... 80h = The color mixing percentage is 50%. ... FFh = The color mixing percentage is 100%.

### 8.6.42 OUT21\_COLOR (Address = 29h) [reset = 00h]

OUT21\_COLOR is shown in 图 62 and described in 表 47.

Return to 表 4.

**图 62. OUT21\_COLOR Register**

7	6	5	4	3	2	1	0
OUT21_COLOR							
R/W-00h							

**表 47. OUT21\_COLOR Register Field Descriptions**

Bit	Field	Type	Reset	Description
7–0	OUT21_COLOR	R/W	00h	00h = The color mixing percentage is 0%. ... 80h = The color mixing percentage is 50%. ... FFh = The color mixing percentage is 100%.

### 8.6.43 OUT22\_COLOR (Address = 2Ah) [reset = 00h]

OUT22\_COLOR is shown in 图 63 and described in 表 48.

Return to 表 4.

**图 63. OUT22\_COLOR Register**

7	6	5	4	3	2	1	0
OUT22_COLOR							
R/W-00h							

**表 48. OUT22\_COLOR Register Field Descriptions**

Bit	Field	Type	Reset	Description
7–0	OUT22_COLOR	R/W	00h	00h = The color mixing percentage is 0%. ... 80h = The color mixing percentage is 50%. ... FFh = The color mixing percentage is 100%.

### 8.6.44 OUT23\_COLOR (Address = 2Bh) [reset = 00h]

OUT23\_COLOR is shown in 图 64 and described in 表 49.

Return to 表 4.

**图 64. OUT23\_COLOR Register**

7	6	5	4	3	2	1	0
OUT23_COLOR							
R/W-00h							

**表 49. OUT23\_COLOR Register Field Descriptions**

Bit	Field	Type	Reset	Description
7–0	OUT23_COLOR	R/W	00h	00h = The color mixing percentage is 0%. ... 80h = The color mixing percentage is 50%. ... FFh = The color mixing percentage is 100%.

#### 8.6.45 OUT24\_COLOR (Address = 2Ch) [reset = 00h]

OUT24\_COLOR is shown in 图 65 and described in 表 50.

Return to 表 4.

**图 65. OUT24\_COLOR Register**

7	6	5	4	3	2	1	0
OUT24_COLOR							
R/W-00h							

**表 50. OUT24\_COLOR Register Field Descriptions**

Bit	Field	Type	Reset	Description
7–0	OUT24_COLOR	R/W	00h	00h = The color mixing percentage is 0%. ... 80h = The color mixing percentage is 50%. ... FFh = The color mixing percentage is 100%.

#### 8.6.46 OUT25\_COLOR (Address = 2Dh) [reset = 00h]

OUT25\_COLOR is shown in 图 66 and described in 表 51.

Return to 表 4.

**图 66. OUT25\_COLOR Register**

7	6	5	4	3	2	1	0
OUT25_COLOR							
R/W-00h							

**表 51. OUT25\_COLOR Register Field Descriptions**

Bit	Field	Type	Reset	Description
7–0	OUT25_COLOR	R/W	00h	00h = The color mixing percentage is 0%. ... 80h = The color mixing percentage is 50%. ... FFh = The color mixing percentage is 100%.

#### 8.6.47 OUT26\_COLOR (Address = 2Eh) [reset = 00h]

OUT26\_COLOR is shown in 图 67 and described in 表 52.

Return to 表 4.

**图 67. OUT26\_COLOR Register**

7	6	5	4	3	2	1	0
OUT26_COLOR							
R/W-00h							

**表 52. OUT26\_COLOR Register Field Descriptions**

Bit	Field	Type	Reset	Description
7–0	OUT26_COLOR	R/W	00h	00h = The color mixing percentage is 0%. ... 80h = The color mixing percentage is 50%. ... FFh = The color mixing percentage is 100%.

#### 8.6.48 OUT27\_COLOR (Address = 2Fh) [reset = 00h]

OUT27\_COLOR is shown in 图 68 and described in 表 53.

Return to 表 4.

**图 68. OUT27\_COLOR Register**

7	6	5	4	3	2	1	0
OUT27_COLOR							
R/W-00h							

**表 53. OUT27\_COLOR Register Field Descriptions**

Bit	Field	Type	Reset	Description
7–0	OUT27_COLOR	R/W	00h	00h = The color mixing percentage is 0%. ... 80h = The color mixing percentage is 50%. ... FFh = The color mixing percentage is 100%.

#### 8.6.49 OUT28\_COLOR (Address = 30h) [reset = 00h]

OUT28\_COLOR is shown in 图 69 and described in 表 54.

Return to 表 4.

**图 69. OUT28\_COLOR Register**

7	6	5	4	3	2	1	0
OUT28_COLOR							
R/W-00h							

**表 54. OUT28\_COLOR Register Field Descriptions**

Bit	Field	Type	Reset	Description
7–0	OUT28_COLOR	R/W	00h	00h = The color mixing percentage is 0%. ... 80h = The color mixing percentage is 50%. ... FFh = The color mixing percentage is 100%.

### 8.6.50 OUT29\_COLOR (Address = 31h) [reset = 00h]

OUT29\_COLOR is shown in 图 70 and described in 表 55.

Return to 表 4.

图 70. OUT29\_COLOR Register

7	6	5	4	3	2	1	0
OUT29_COLOR							
R/W-00h							

表 55. OUT29\_COLOR Register Field Descriptions

Bit	Field	Type	Reset	Description
7–0	OUT29_COLOR	R/W	00h	00h = The color mixing percentage is 0%. ... 80h = The color mixing percentage is 50%. ... FFh = The color mixing percentage is 100%.

### 8.6.51 OUT30\_COLOR (Address = 32h) [reset = 00h]

OUT30\_COLOR is shown in 图 71 and described in 表 56.

Return to 表 4.

图 71. OUT30\_COLOR Register

7	6	5	4	3	2	1	0
OUT30_COLOR							
R/W-00h							

表 56. OUT30\_COLOR Register Field Descriptions

Bit	Field	Type	Reset	Description
7–0	OUT30_COLOR	R/W	00h	00h = The color mixing percentage is 0%. ... 80h = The color mixing percentage is 50%. ... FFh = The color mixing percentage is 100%.

### 8.6.52 OUT31\_COLOR (Address = 33h) [reset = 00h]

OUT31\_COLOR is shown in 图 72 and described in 表 57.

Return to 表 4.

图 72. OUT31\_COLOR Register

7	6	5	4	3	2	1	0
OUT31_COLOR							
R/W-00h							

**表 57. OUT31\_COLOR Register Field Descriptions**

Bit	Field	Type	Reset	Description
7–0	OUT31_COLOR	R/W	00h	00h = The color mixing percentage is 0%. ... 80h = The color mixing percentage is 50%. ... FFh = The color mixing percentage is 100%.

#### 8.6.53 OUT32\_COLOR (Address = 34h) [reset = 00h]

OUT32\_COLOR is shown in 图 73 and described in 表 58.

Return to 表 4.

**图 73. OUT32\_COLOR Register**

7	6	5	4	3	2	1	0
OUT32_COLOR							
R/W-00h							

**表 58. OUT32\_COLOR Register Field Descriptions**

Bit	Field	Type	Reset	Description
7–0	OUT32_COLOR	R/W	00h	00h = The color mixing percentage is 0%. ... 80h = The color mixing percentage is 50%. ... FFh = The color mixing percentage is 100%.

#### 8.6.54 OUT33\_COLOR (Address = 35h) [reset = 00h]

OUT33\_COLOR is shown in 图 74 and described in 表 59.

Return to 表 4.

**图 74. OUT33\_COLOR Register**

7	6	5	4	3	2	1	0
OUT33_COLOR							
R/W-00h							

**表 59. OUT33\_COLOR Register Field Descriptions**

Bit	Field	Type	Reset	Description
7–0	OUT33_COLOR	R/W	00h	00h = The color mixing percentage is 0%. ... 80h = The color mixing percentage is 50%. ... FFh = The color mixing percentage is 100%.

#### 8.6.55 OUT34\_COLOR (Address = 36h) [reset = 00h]

OUT34\_COLOR is shown in 图 75 and described in 表 60.

Return to 表 4.

**图 75. OUT34\_COLOR Register**

7	6	5	4	3	2	1	0
OUT34_COLOR							
R/W-00h							

**表 60. OUT34\_COLOR Register Field Descriptions**

Bit	Field	Type	Reset	Description
7–0	OUT34_COLOR	R/W	00h	00h = The color mixing percentage is 0%. ... 80h = The color mixing percentage is 50%. ... FFh = The color mixing percentage is 100%.

#### 8.6.56 OUT35\_COLOR (Address = 37h) [reset = 00h]

OUT35\_COLOR is shown in 图 76 and described in 表 61.

Return to 表 4.

**图 76. OUT35\_COLOR Register**

7	6	5	4	3	2	1	0
OUT35_COLOR							
R/W-00h							

**表 61. OUT35\_COLOR Register Field Descriptions**

Bit	Field	Type	Reset	Description
7–0	OUT35_COLOR	R/W	00h	00h = The color mixing percentage is 0%. ... 80h = The color mixing percentage is 50%. ... FFh = The color mixing percentage is 100%.

#### 8.6.57 RESET (Address = 38h) [reset = 00h]

RESET is shown in 图 77 and described in 表 62.

Return to 表 4.

**图 77. RESET Register**

7	6	5	4	3	2	1	0
RESET							
W-00h							

**表 62. RESET Register Field Descriptions**

Bit	Field	Type	Reset	Description
7–0	RESET	W	00h	FFh = Reset all the registers to default value.

## 9 Application and Implementation

### 注

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

### 9.1 Application Information

The LP503x device is a 30- or 36-channel constant-current-sink LED driver. The LP503x device improves the user experience in color mixing and intensity control, for both live effects and coding effort. The optimized performance for RGB LEDs makes it a perfect fit for human-machine interaction applications.

### 9.2 Typical Application

The LP503x design supports up to four devices in parallel with different configurations on the ADDR0 and ADDR1 pins.

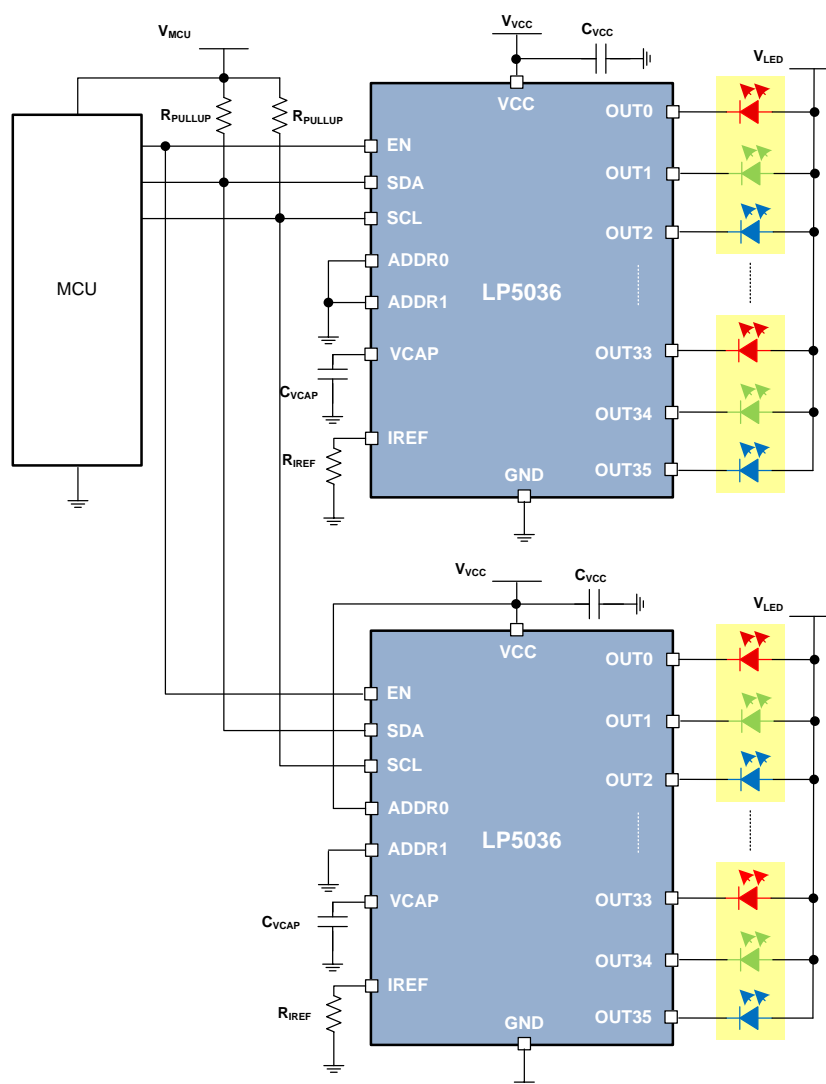


图 78. Driving Dual LP5036 Application Example

## Typical Application (接下页)

### 9.2.1 Design Requirements

Set the LED current to 15 mA using the  $R_{IREF}$  resistor.

### 9.2.2 Detailed Design Procedure

The LP503x device scales up the reference current ( $I_{REF}$ ) set by the external resistor ( $R_{IREF}$ ) to sink the output current ( $I_{OUT}$ ) at each output port. can be used to calculate the target output current  $I_{MAX\_SET}$ :

$$R_{IREF} = \frac{K_{IREF} \times V_{IREF}}{I_{(MAX\_SET)}} = 105 \times 0.7 \div 0.015 = 4900 \, \Omega$$

The SCL and SDA lines must each have a pullup resistor placed somewhere on the line (the pullup resistors are normally located on the bus master). In typical applications, values of 1.8 k $\Omega$  to 4.7 k $\Omega$  are used, depending on the bus capacitance, I/O voltage, and the desired communication speed. Selecting a smaller value increases the pullup speed, but slows the pulldown speed. If they want pull up quickly select the samller one but it will impact the pull down speed.

VCAP is the internal LDO output pin. This pin must be connected through a 1- $\mu$ F capacitor to GND. Put the capacitor as close to the device as possible.

TI recommends having a 1- $\mu$ F capacitor between VCC and GND to ensure proper operation. Put the capacitor as close to the device as possible.

### 9.2.3 Application Curves

The test condition for is that the testing is under bank control, using the following register values: 0x02 (0xFF), 0x04 (0xF0), 0x05 (0xF0), 0x06 (0xF0). The test condition for is that the testing is under bank control, using the following register values: 0x02 (0xFF), 0x04 (0x0F), 0x05 (0x0F), 0x06 (0x0F).

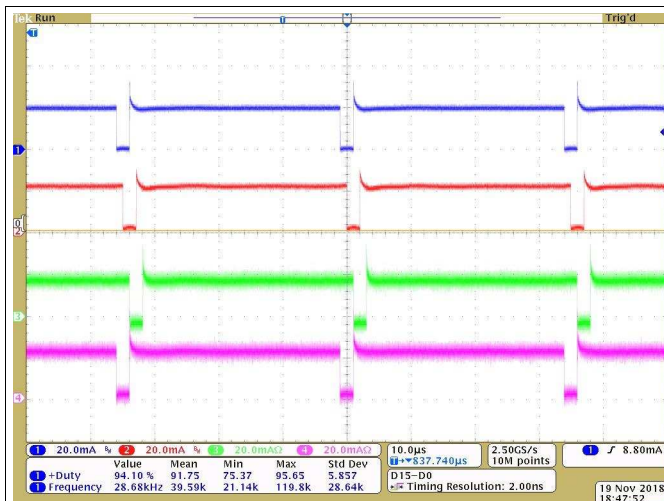


图 79. Current Waveform of OUT0, OUT1, OUT2 and OUT3

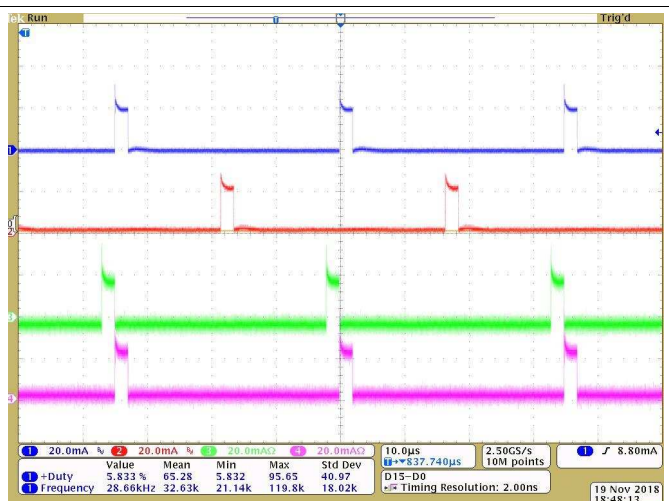


图 80. Current Waveform of OUT0, OUT1, OUT2 and OUT3

## 10 Power Supply Recommendations

The device is designed to operate from a  $V_{VCC}$  input-voltage supply range between 2.7 V and 5.5 V. This input supply must be well-regulated and able to withstand maximum input current and maintain stable voltage without voltage drop even in a load-transition condition (start-up or rapid intensity change). The resistance of the input supply rail must be low enough that the input-current transient does not cause a drop below the 2.7-V level in the LP503x  $V_{VCC}$  supply voltage.

## 11 Layout

### 11.1 Layout Guidelines

To prevent thermal shutdown, the junction temperature,  $T_J$ , must be less than  $T_{(TSD)}$ . If the voltage drop across the output channels is high, the device power dissipation can be large. The LP503x device has very good thermal performance because of the thermal pad design; however, the PCB layout is also very important to ensure that the device has good thermal performance. Good PCB design can optimize heat transfer, which is essential for the long-term reliability of the device.

Use the following guidelines when designing the device layout:

- Put the  $C_{VAP}$ ,  $C_{VCC}$  and  $R_{REF}$  as close as possible to the device. Also, TI recommends placing the ground plane as shown in [Figure 81](#) and [Figure 82](#).
- Maximize the copper coverage on the PCB to increase the thermal conductivity of the board. The major heat flow path from the package to the ambient is through copper on the PCB. Maximum copper density is extremely important when no heat sinks are attached to the PCB on the other side from the package.
- Add as many thermal vias as possible directly under the package ground pad to maximize the thermal conductivity of the board.
- Use either plated-shut or plugged and capped vias for all the thermal vias on both sides of the board to prevent solder voids. To ensure reliability and performance, the solder coverage must be at least 85%.

## LP5030, LP5036

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### 11.2 Layout Examples

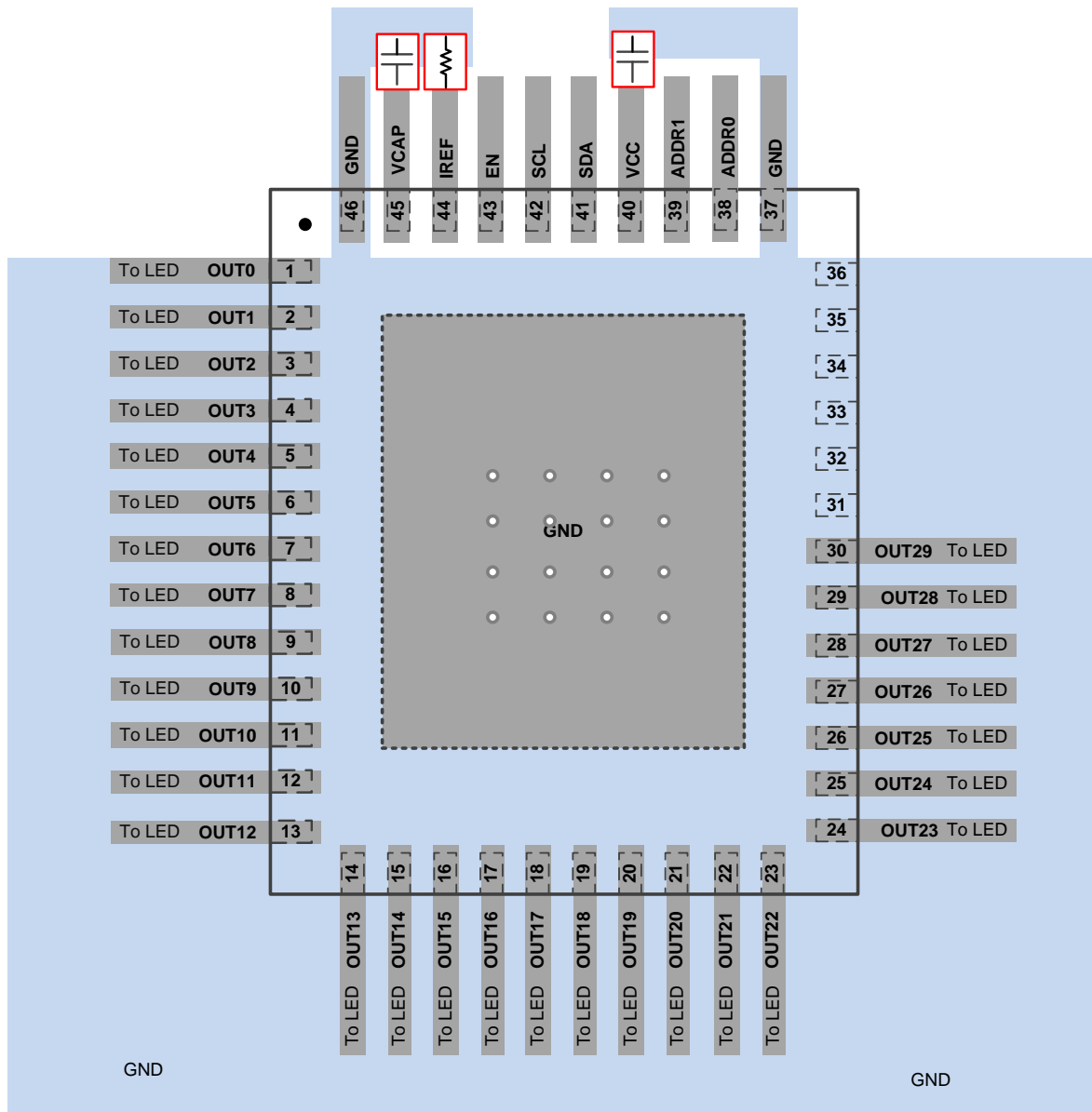


图 81. LP5030 Layout Example

## Layout Examples (接下页)

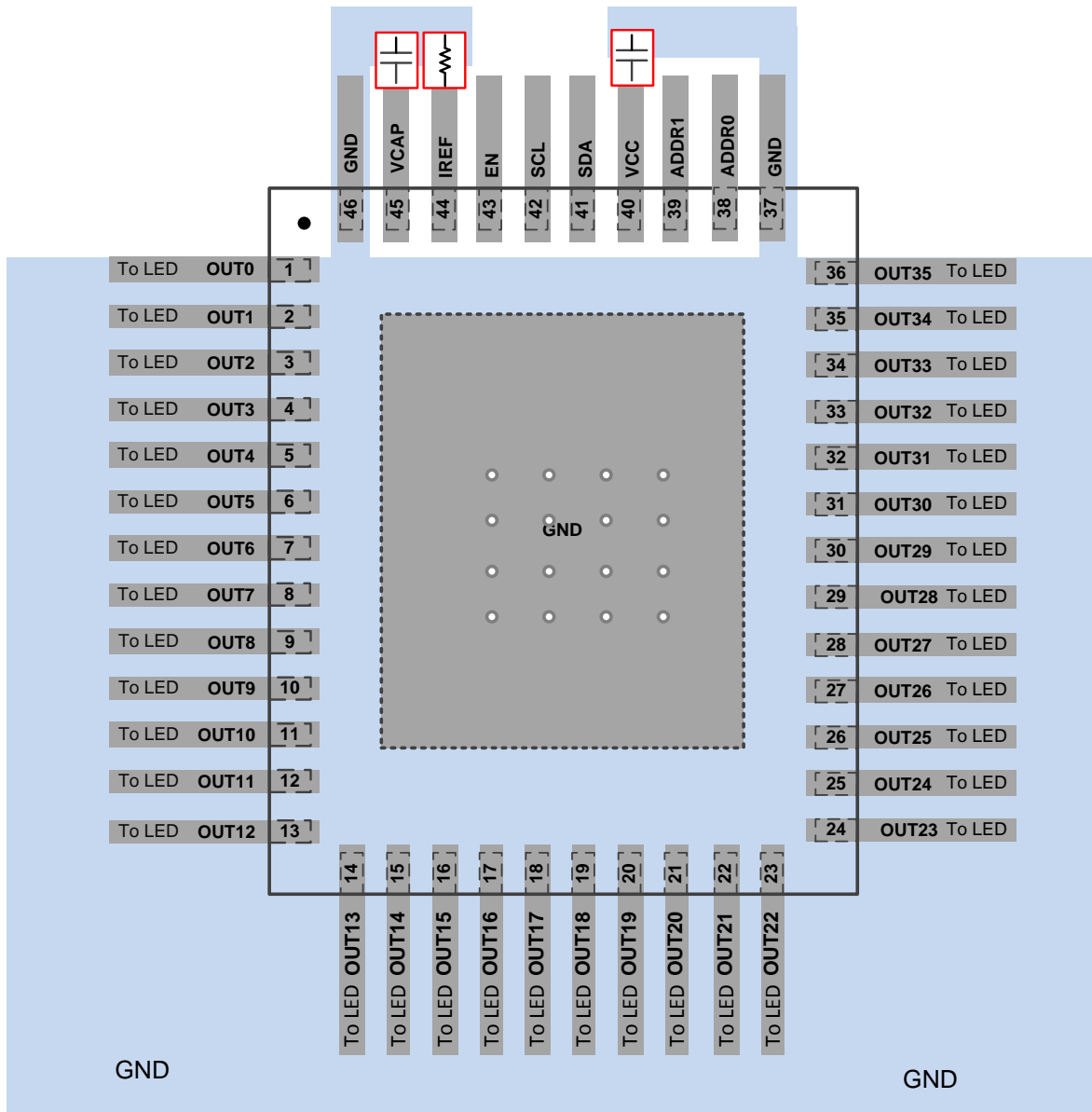


图 82. LP5036 Layout Example

## 12 器件和文档支持

### 12.1 相关链接

下表列出了快速访问链接。类别包括技术文档、支持和社区资源、工具和软件，以及立即订购快速访问。

表 63. 相关链接

器件	产品文件夹	立即订购	技术文档	工具与软件	支持和社区
LP5030	<a href="#">请单击此处</a>	<a href="#">请单击此处</a>	<a href="#">请单击此处</a>	<a href="#">请单击此处</a>	<a href="#">请单击此处</a>
LP5036	<a href="#">请单击此处</a>	<a href="#">请单击此处</a>	<a href="#">请单击此处</a>	<a href="#">请单击此处</a>	<a href="#">请单击此处</a>

### 12.2 接收文档更新通知

要接收文档更新通知，请导航至 [TI.com.cn](#) 上的器件产品文件夹。单击右上角的 [通知我](#) 进行注册，即可每周接收产品信息更改摘要。有关更改的详细信息，请查看任何已修订文档中包含的修订历史记录。

### 12.3 社区资源

下列链接提供到 TI 社区资源的连接。链接的内容由各个分销商“按照原样”提供。这些内容并不构成 TI 技术规范，并且不一定反映 TI 的观点；请参阅 TI 的 [《使用条款》](#)。

**TI E2E™ 在线社区** *TI 的工程师对工程师 (E2E) 社区*。此社区的创建目的在于促进工程师之间的协作。在 [e2e.ti.com](#) 中，您可以咨询问题、分享知识、拓展思路并与同行工程师一道帮助解决问题。

**设计支持** *TI 参考设计支持* 可帮助您快速查找有帮助的 E2E 论坛、设计支持工具以及技术支持的联系信息。

### 12.4 商标

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### 12.5 静电放电警告



ESD 可能会损坏该集成电路。德州仪器 (TI) 建议通过适当的预防措施处理所有集成电路。如果不遵守正确的处理措施和安装程序，可能会损坏集成电路。

ESD 的损坏小至导致微小的性能降级，大至整个器件故障。精密的集成电路可能更容易受到损坏，这是因为非常细微的参数更改都可能会导致器件与其发布的规格不相符。

### 12.6 术语表

**SLYZ022** — *TI 术语表*。

这份术语表列出并解释术语、缩写和定义。

## 13 机械、封装和可订购信息

以下页面包含机械、封装和可订购信息。这些信息是适用于指定器件的最新数据。数据如有变更，恕不另行通知，且不会对此文档进行修订。如需获取此数据表的浏览器版本，请查看左侧的导航面板。

## PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
LP5030RJVR	ACTIVE	VQFN	RJV	46	3000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LP5030	<a href="#">Samples</a>
LP5036RJVR	ACTIVE	VQFN	RJV	46	3000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LP5036	<a href="#">Samples</a>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

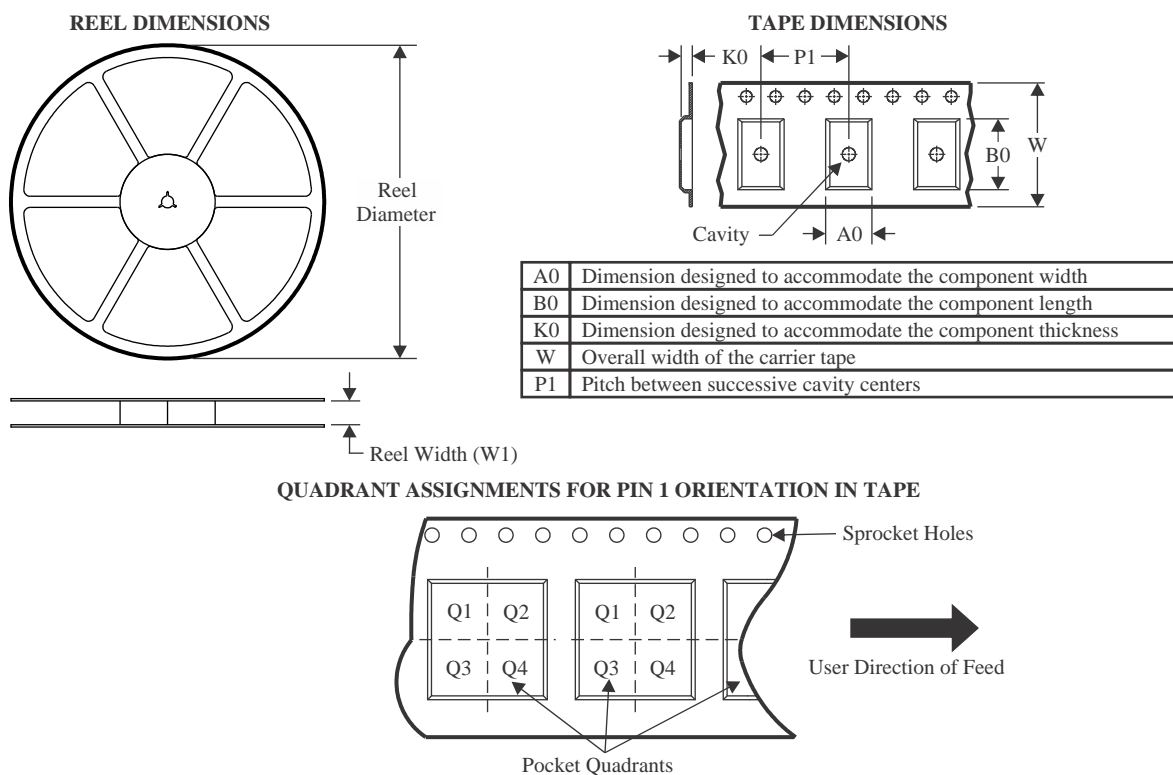
(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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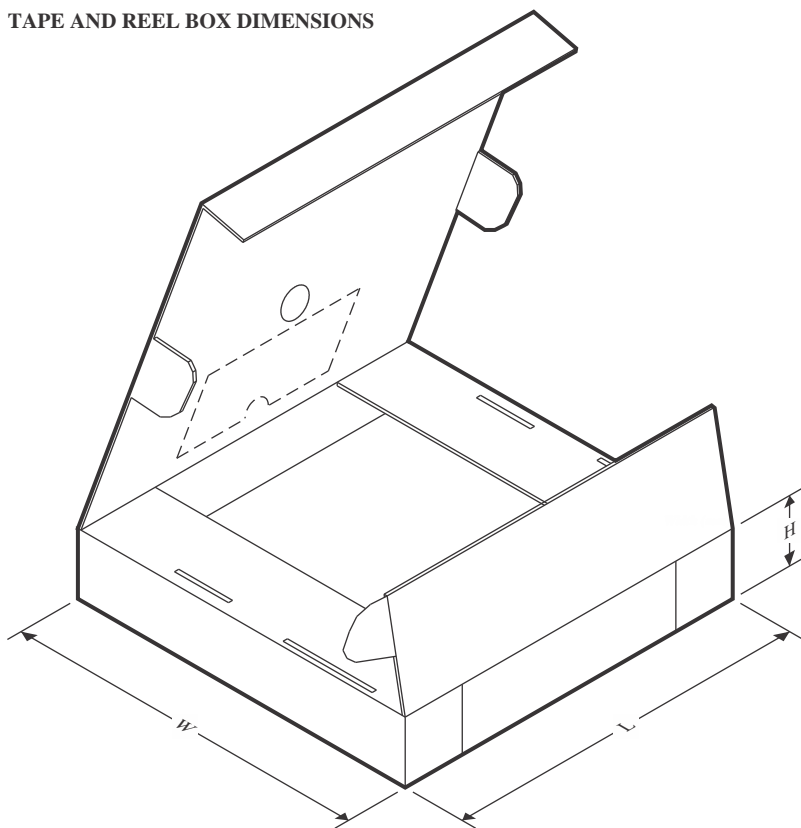
## TAPE AND REEL INFORMATION



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LP5030RJVR	VQFN	RJV	46	3000	330.0	12.4	5.3	6.3	1.15	8.0	12.0	Q1
LP5036RJVR	VQFN	RJV	46	3000	330.0	12.4	5.3	6.3	1.15	8.0	12.0	Q1

## TAPE AND REEL BOX DIMENSIONS



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LP5030RJVR	VQFN	RJV	46	3000	367.0	367.0	35.0
LP5036RJVR	VQFN	RJV	46	3000	367.0	367.0	35.0

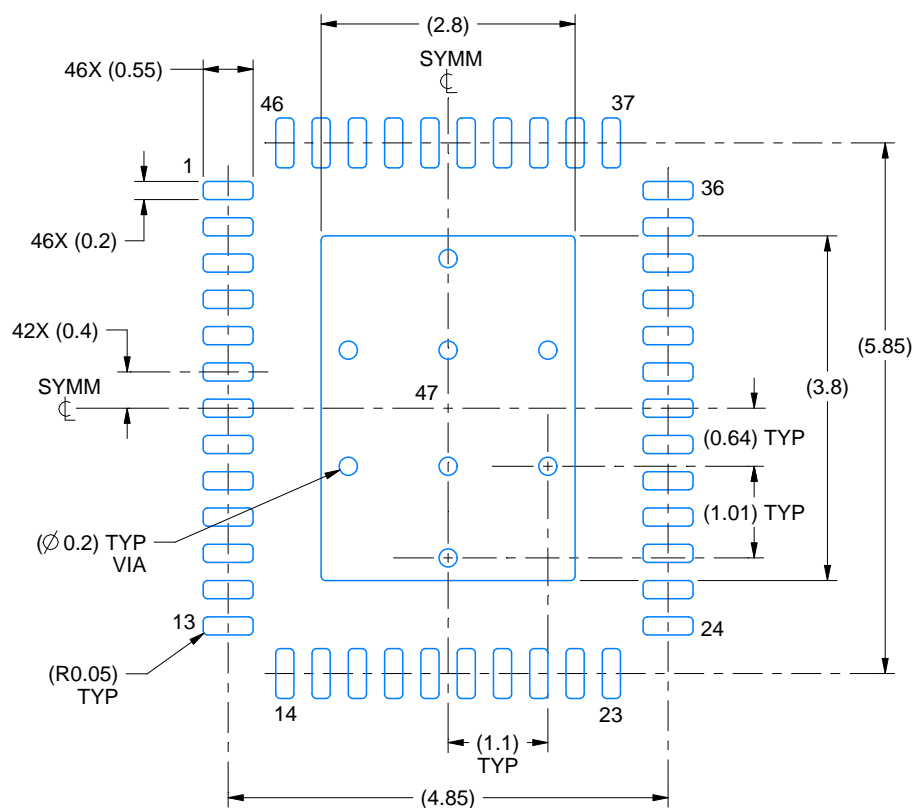
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pad must be soldered to the printed circuit board for thermal and mechanical performance.

# EXAMPLE BOARD LAYOUT

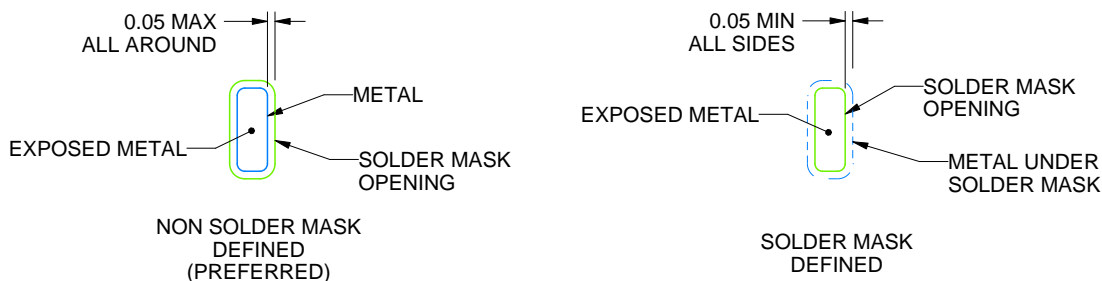
RJV0046A

VQFN - 1 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE:12X



SOLDER MASK DETAILS

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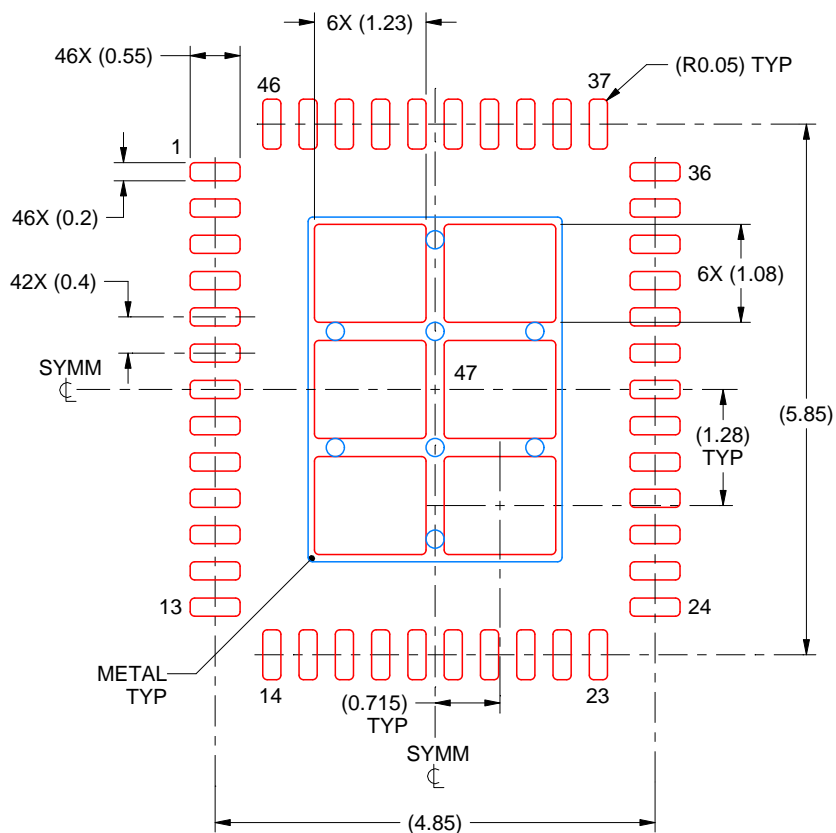
NOTES: (continued)

- This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 ([www.ti.com/lit/slue271](http://www.ti.com/lit/slue271)).
- Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.

**RJV0046A**

### VQFN - 1 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



## SOLDER PASTE EXAMPLE BASED ON 0.1 mm THICK STENCIL

EXPOSED PAD 47:  
75% PRINTED SOLDER COVERAGE BY AREA UNDER PACKAGE  
SCALE:12X

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NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

## 重要声明和免责声明

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